

Knotenimpedanzanalyse – eine alternative Prüfmethode für den Kleinserientest und Reparaturreinatz

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Funktionstest

- Prüft bauteilinterne Funktionen, korrekte Programmierung etc.
- Findet auch dynamische und thermische Fehler
- Erfordert Grundfunktionsfähigkeit
- Findet häufig keine fehlenden C's
- Test unter Versorgung → Gefahr von Folgefehlern
- Häufig komplexere Testaufbauten nötig
- Sucht Fehlerauswirkung, nicht Fehlerursache

In-Circuit-Test

- Prüft Bauteile auf korrekte Werte, Polung, bauteilinterne Funktionen, korrekte Programmierung etc.
- Hoher Durchsatz
- Komplexe Programmierung
- Erfordert digitale Prüfmuster für IC's
- Aufwändige Kontaktierung (Nadelbett oder Flying Probe)
- Für Reparatüreinsatz zu unflexibel

Boundary-Scan-Test

- Einfache Kontaktierung
- Prüft komplexe IC's
- Komplexe Programmierung
- Häufig keine ausreichende Fehlerabdeckung für diskrete Bauteile

Visual Inspection

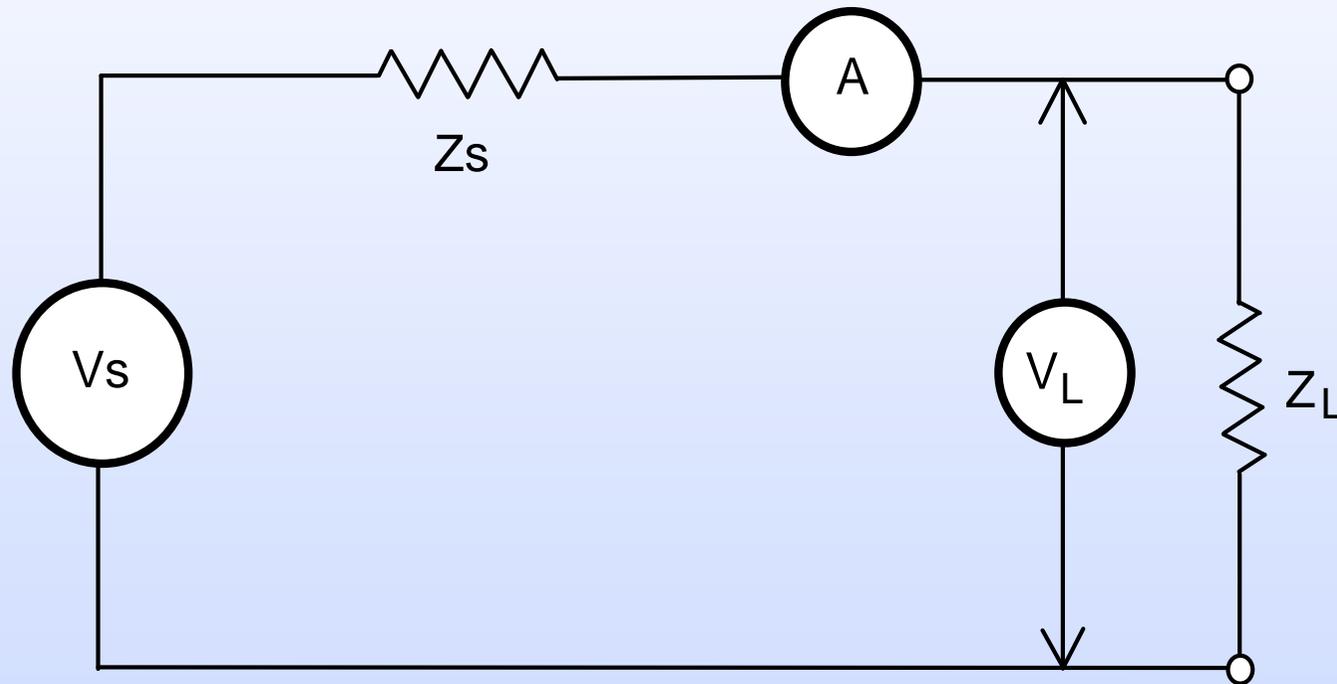
- Hoher Durchsatz
- Texterkennung, IC-Typen etc.

- Komplexe Programmierung
- Eingeschränkte Erkennung falscher Bauteilwerte
- Findet keine Kurzschlüsse unterhalb Bauteile bzw. in der Leiterplatte

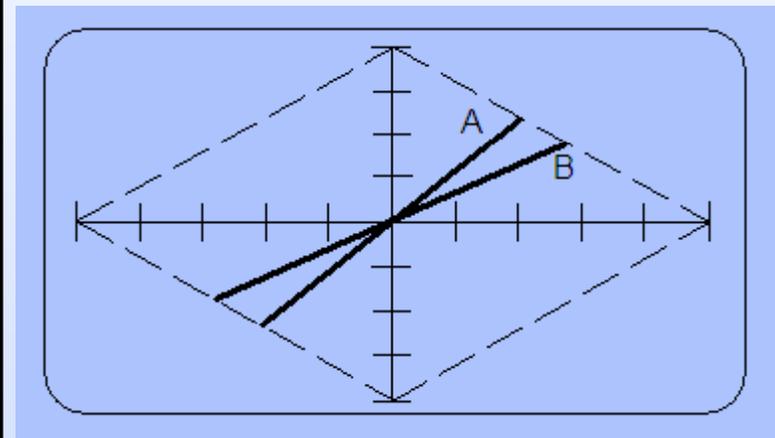
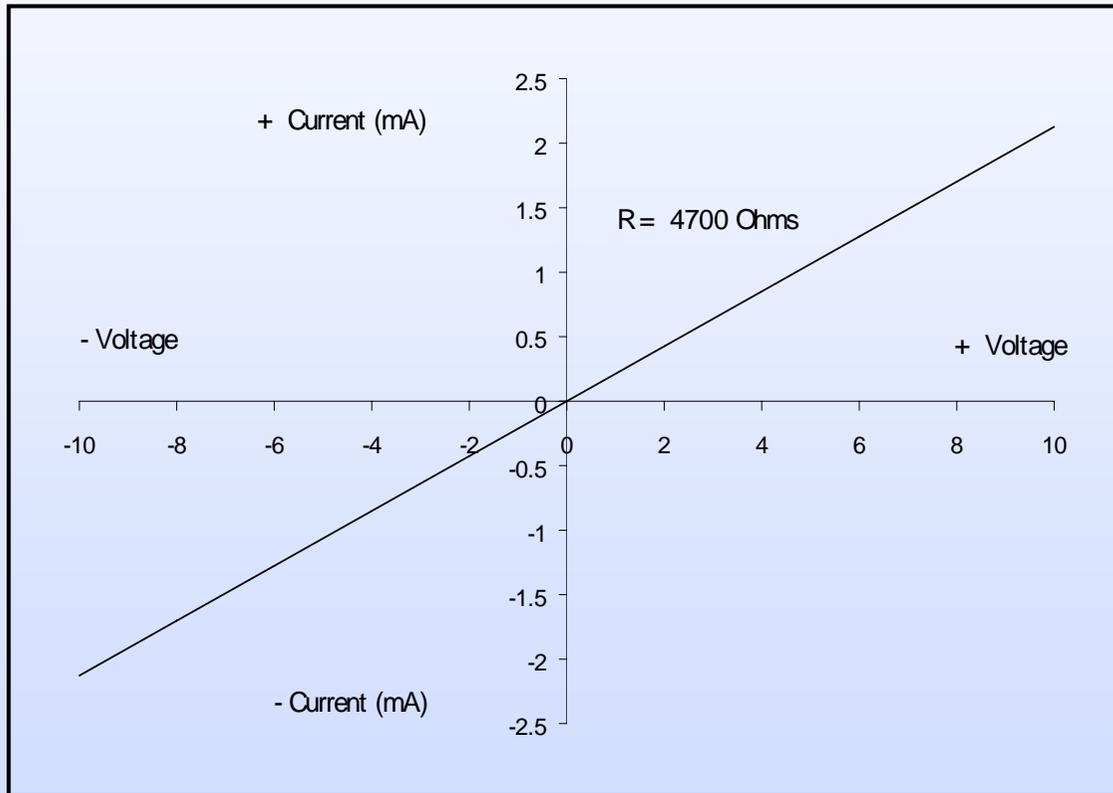
Knotenimpedanzanalyse

- Findet typische Fertigungsfehler, defekte Bauteile
- Keine Bauteilbibliothek erforderlich
- Technologieunabhängig
- Test im stromlosen Zustand
- Einfache Programmierung (Gutmuster)
- Eingeschränkte Erkennung bauteilinterner Fehler
- Mißt keine Bauteilwerte/Toleranzen
- Keine dynamische/thermische Fehler
- Interpretationsfähigkeit durch Bediener nötig

Das Funktionsprinzip



Strom/Spannungsdarstellung

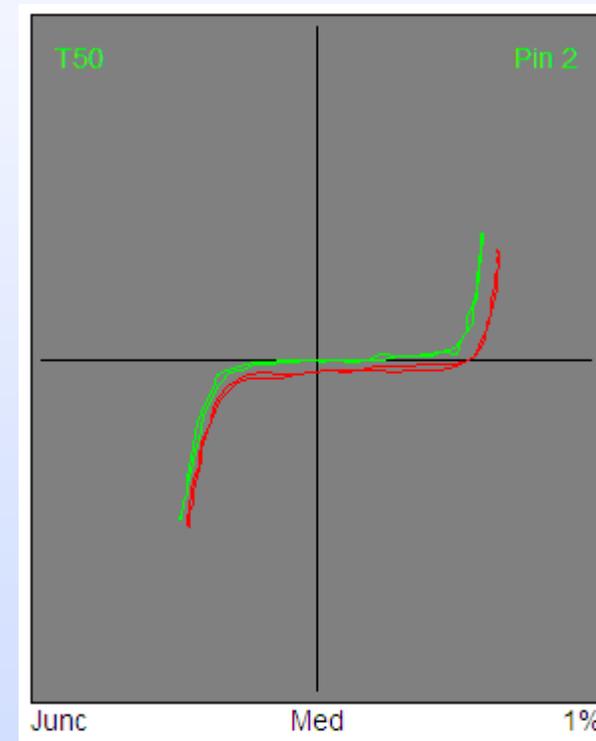


Signaturvergleich

- Kalibrierung des Meßaufbaus
- 100 Meßpunkte entlang einer Sinusperiode
- Messung am Prüfling
- Vergleich der Signaturen

$$D = 1/n \sum_1^n |V_{an} - V_{bn}| \times k\%$$

- Gewichtung

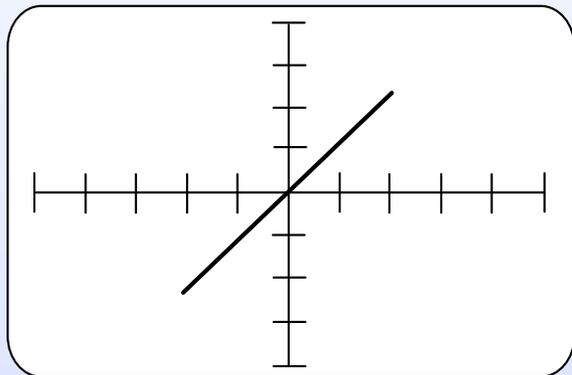


Die Testspannungen/Frequenzen

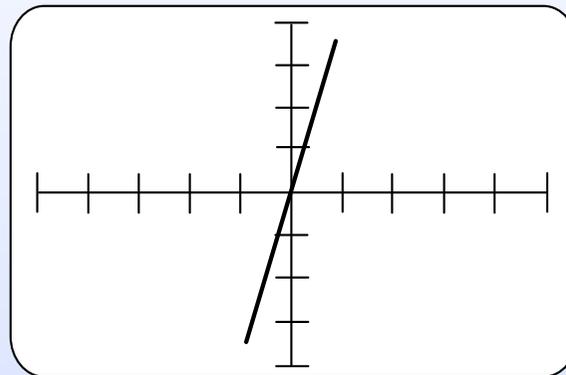
Bereich	Spitzenspannung	Spitzenstrom
Junction	1V	500 μ A
Logic	10V	5mA
Low	10V	150mA
Med	20V	1mA
High	40V	1mA

90 Hz, 500 Hz, 2 kHz

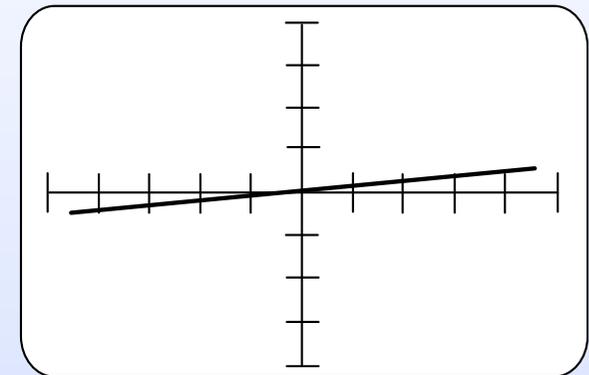
Widerstandsmessung



2K Widerstand
Logic Bereich
Low Frequenz

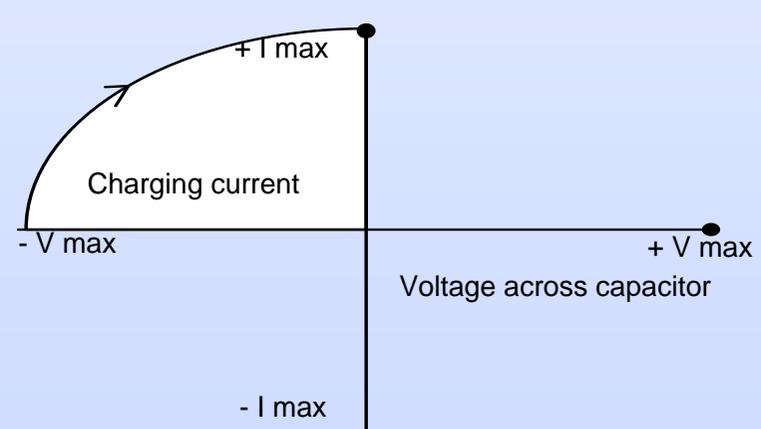
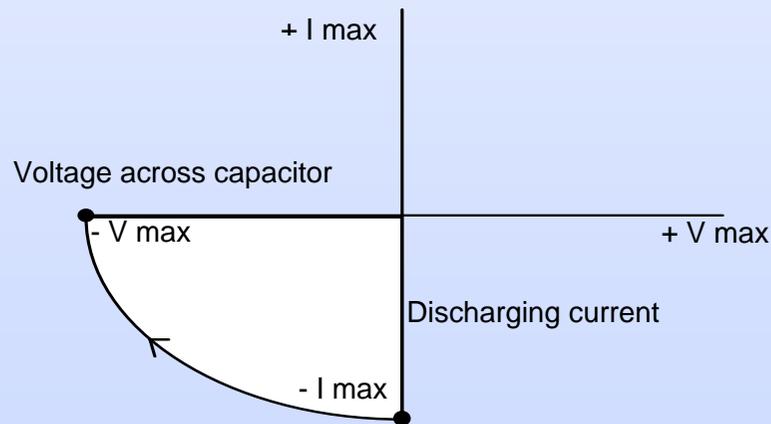
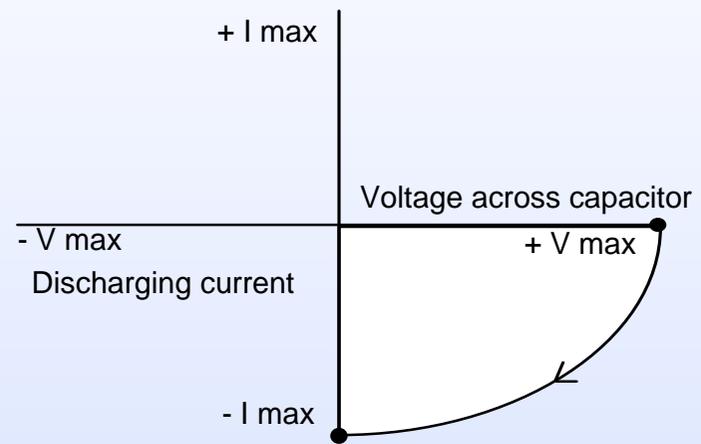
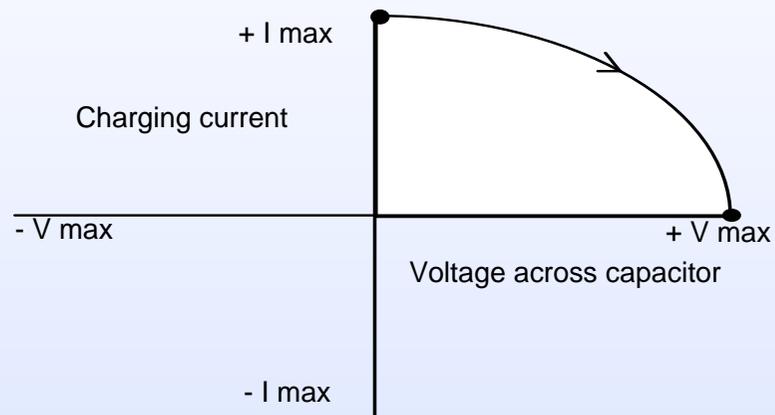


10K Widerstand
High Bereich
Low Frequenz

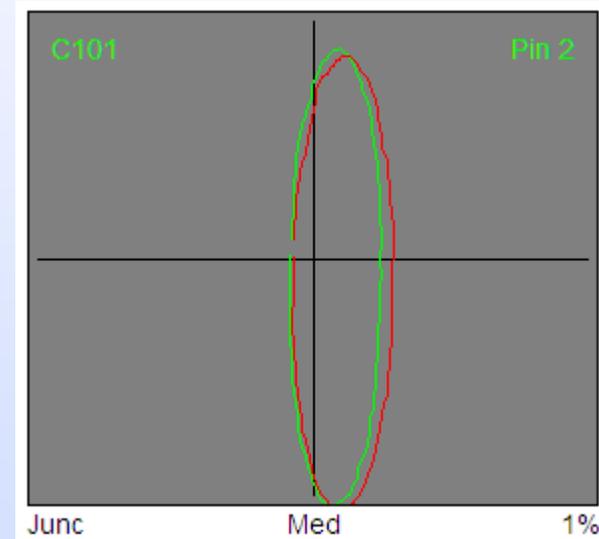
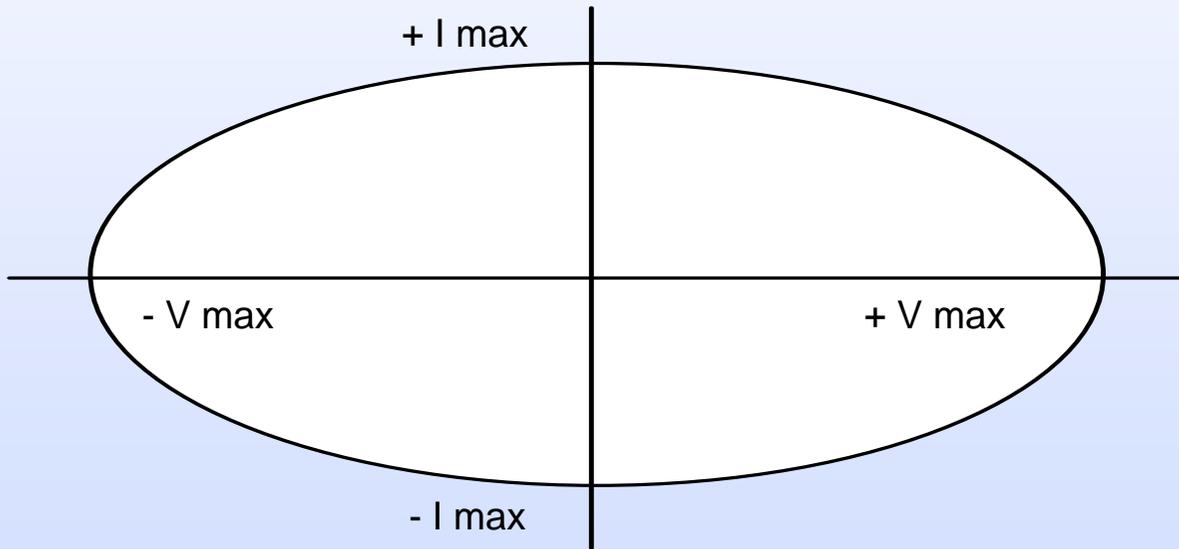


270K Widerstand
High Bereich
Low Frequenz

Test von Kondensatoren



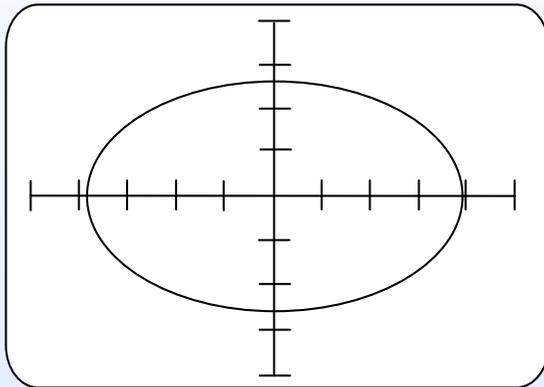
Test von Kondensatoren



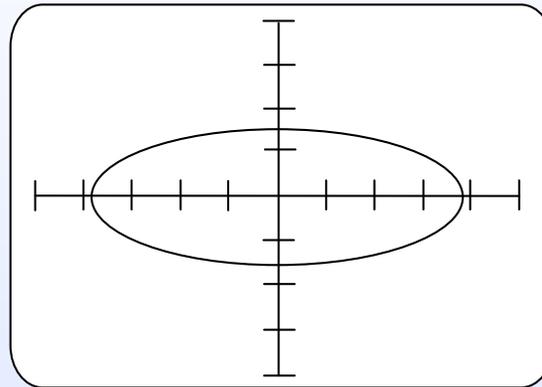
Kapazitive Reaktanz

$$X_c = \frac{1}{2\pi f C}$$

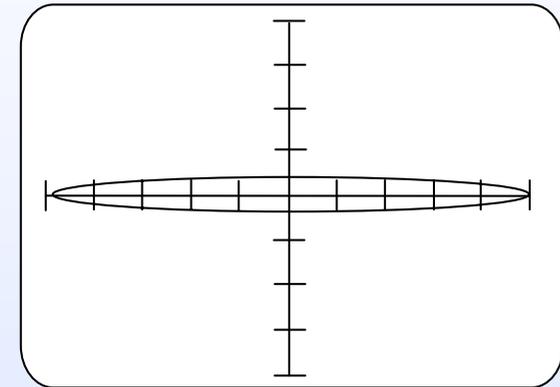
Kapazitätsmessung



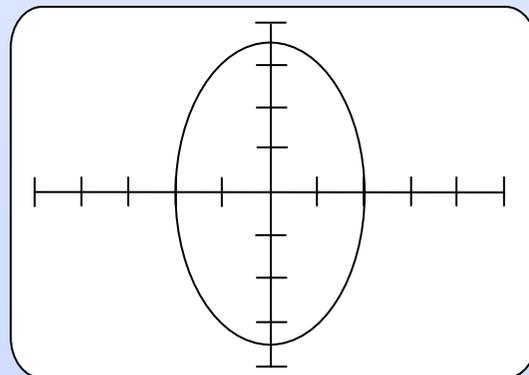
22uF Kondensator
Low Bereich
Low Frequenz



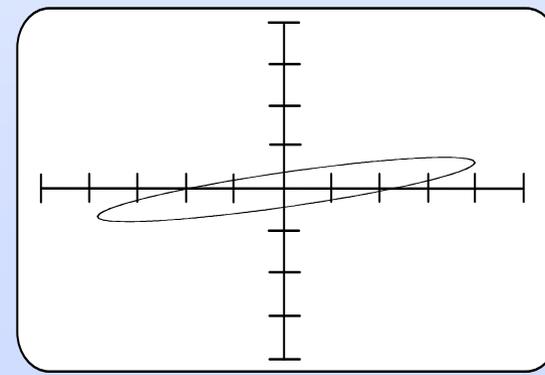
10uF Kondensator
Low Bereich
Low Frequenz



82pF Kondensator
High Bereich
High Frequenz

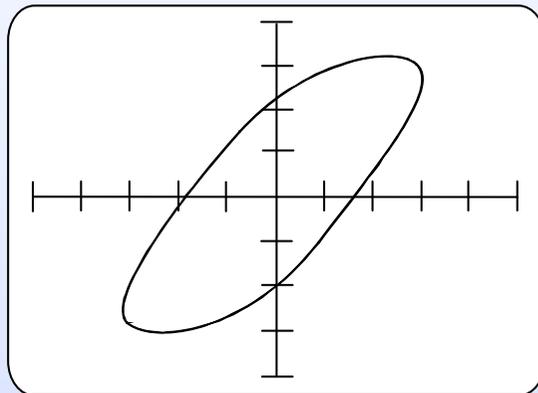


47uF Kondensator
Low Bereich
Low Frequenz
Gutes Bauteil

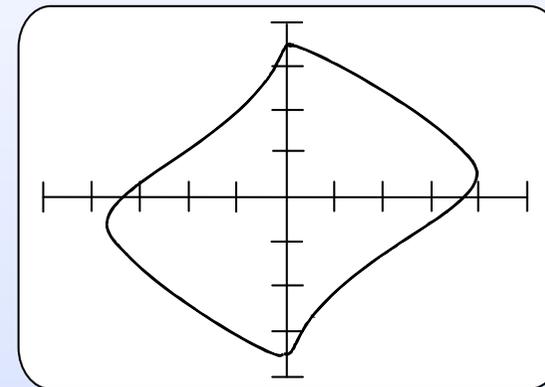


47uF Kondensator
Low Bereich
Low Frequenz
Defekter
Kondensator mit
ohmschen Anteil

Induktivitätsmessung

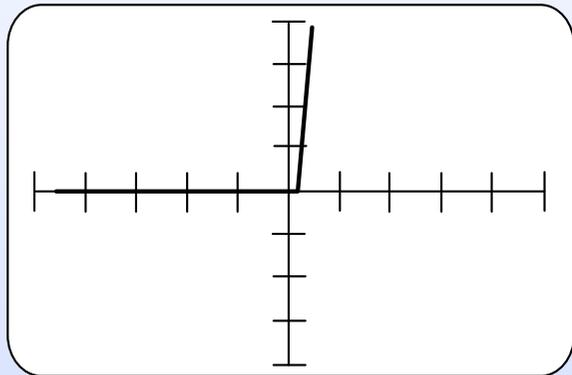


Ferrittransformator
Primärseite
Low Bereich
High Frequenz

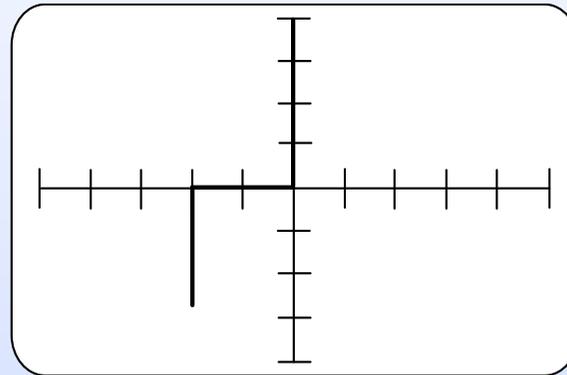


Ferrittransformator
Primärseite
Low Bereich
High Frequenz
Kurzgeschlossene
Windung

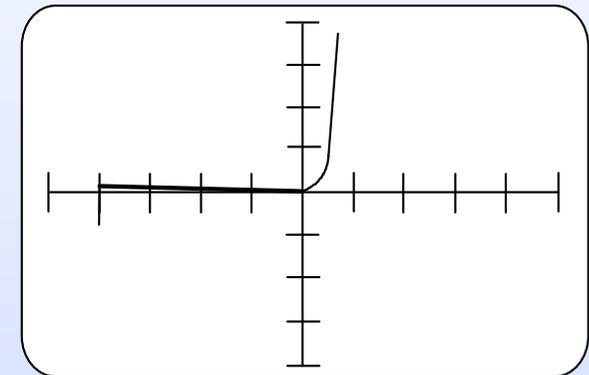
Test von Halbleitern



Kleinsignaldiode
Logic Bereich
Low Frequenz

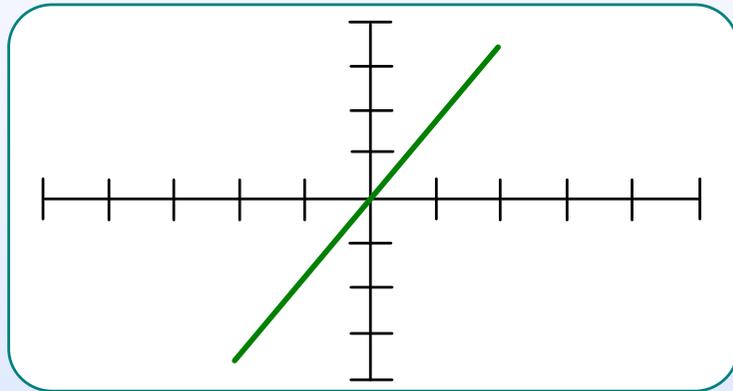


8.2V Zenerdiode
Med Bereich
Low Frequenz

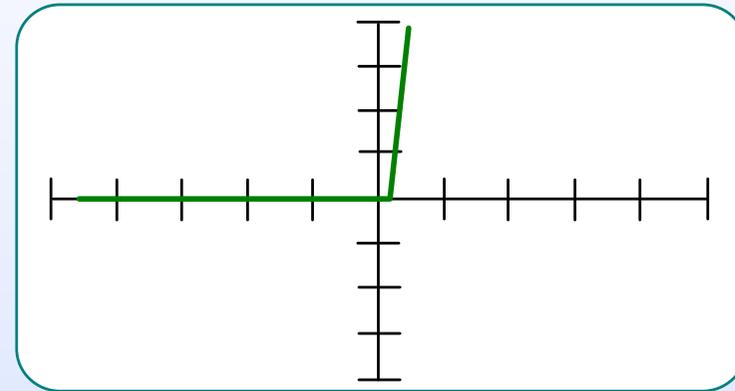


NPN Transistor
Basis-Emitter
Med Bereich
Low Frequenz

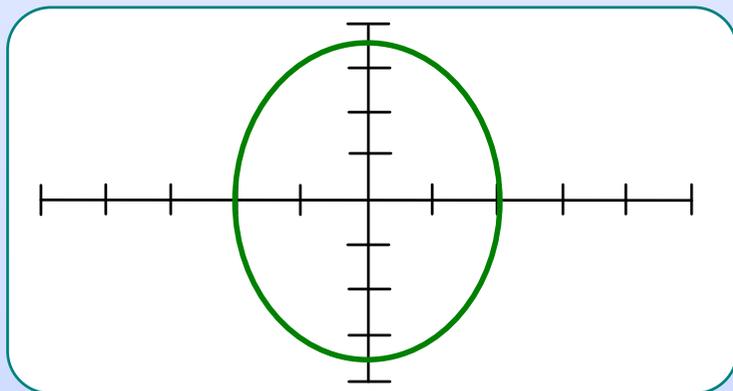
Parallelschaltung von Bauteilen



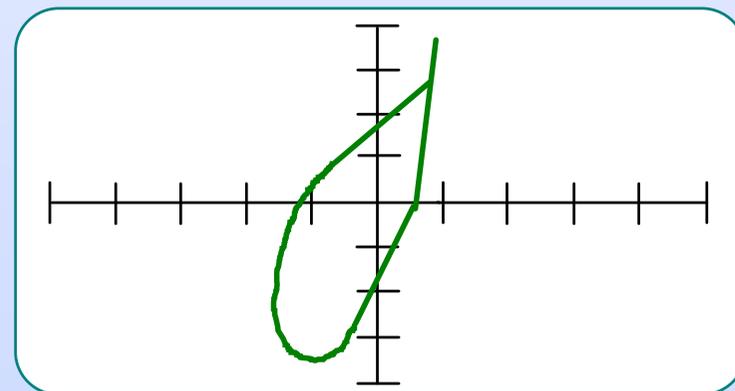
Widerstand



Diode

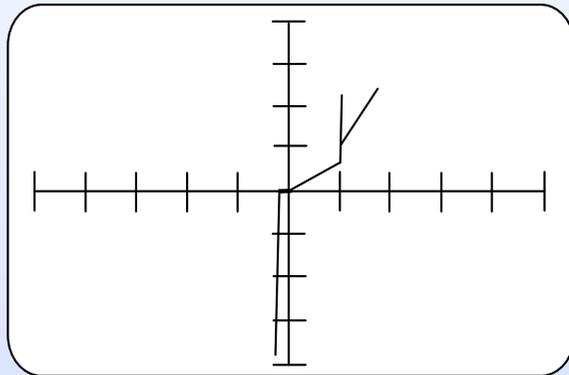


Kondensator

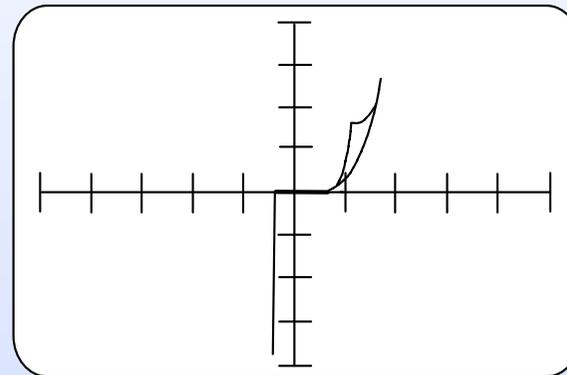


Parallelschaltung

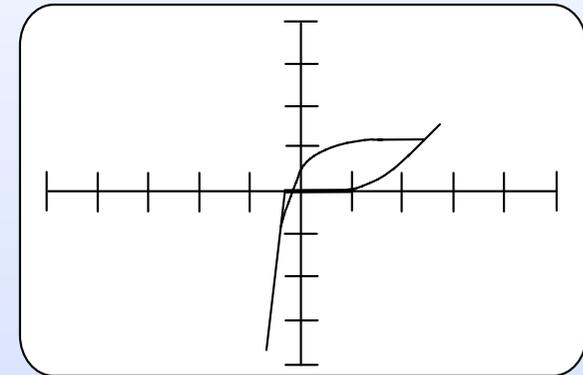
Test von IC's



74LS00
Logic Bereich
Low Frequenz
Ausgang gegen Masse

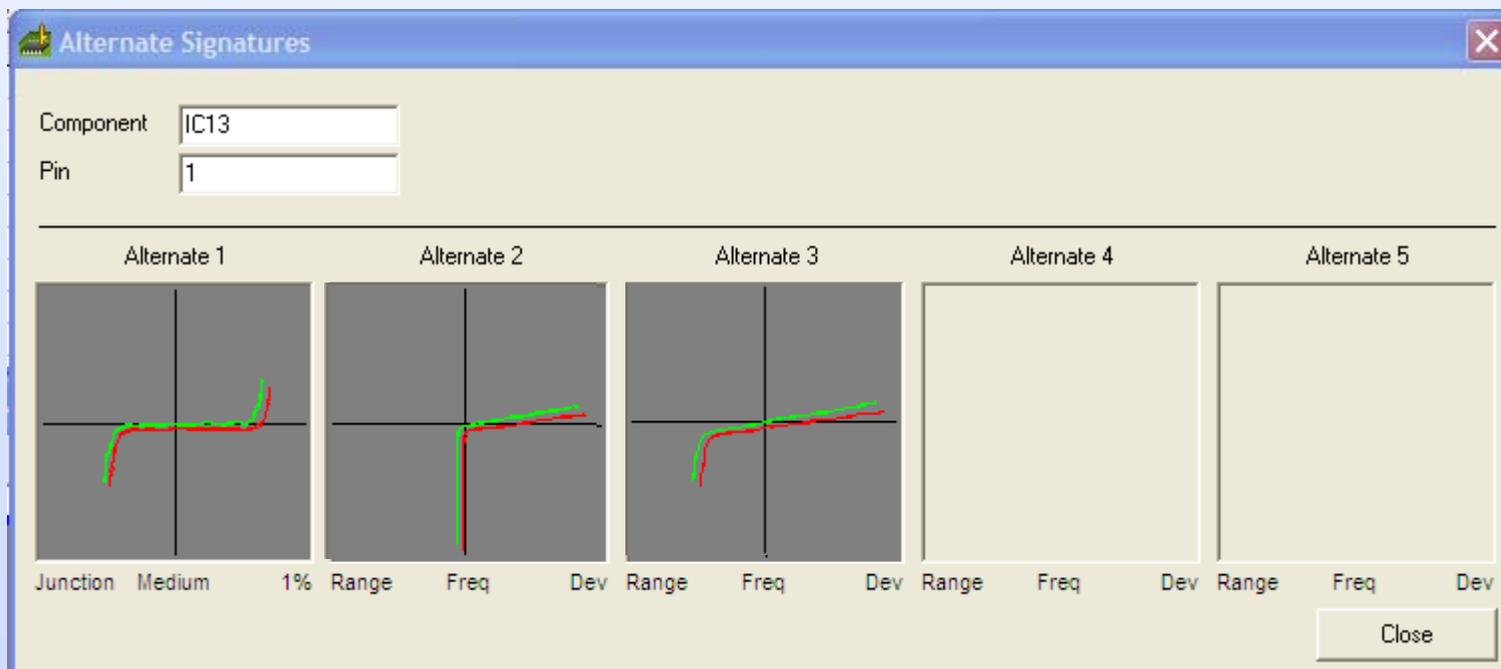
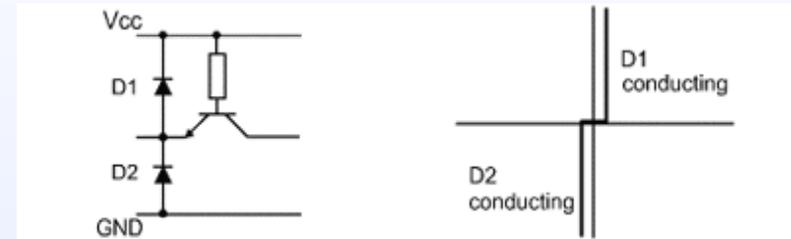
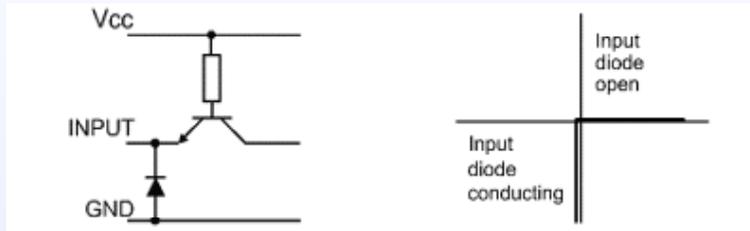


74HC02
Logic Bereich
Low Frequenz
Ausgang gegen Masse

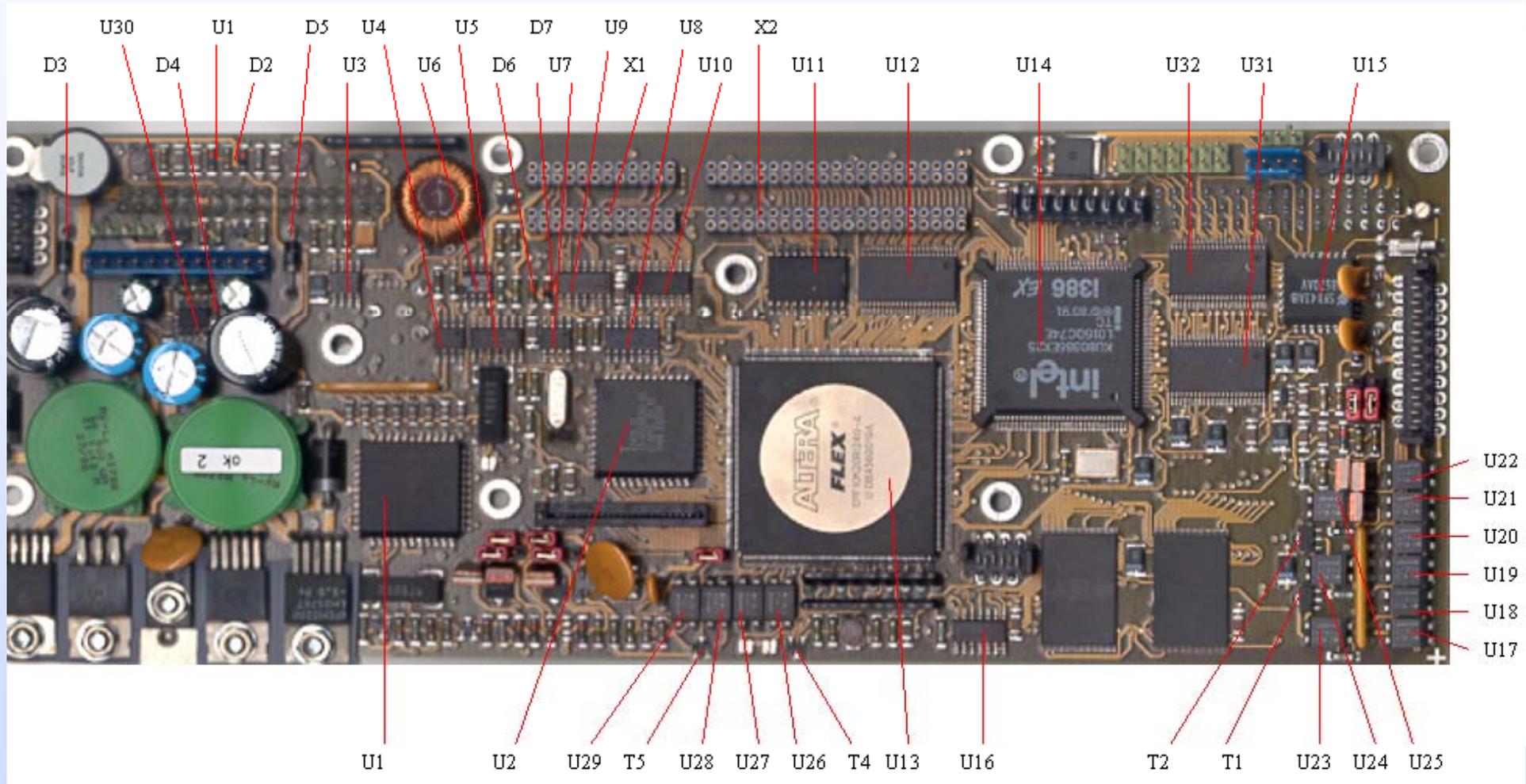


4017
Logic Bereich
Low Frequenz
Ausgang gegen Masse

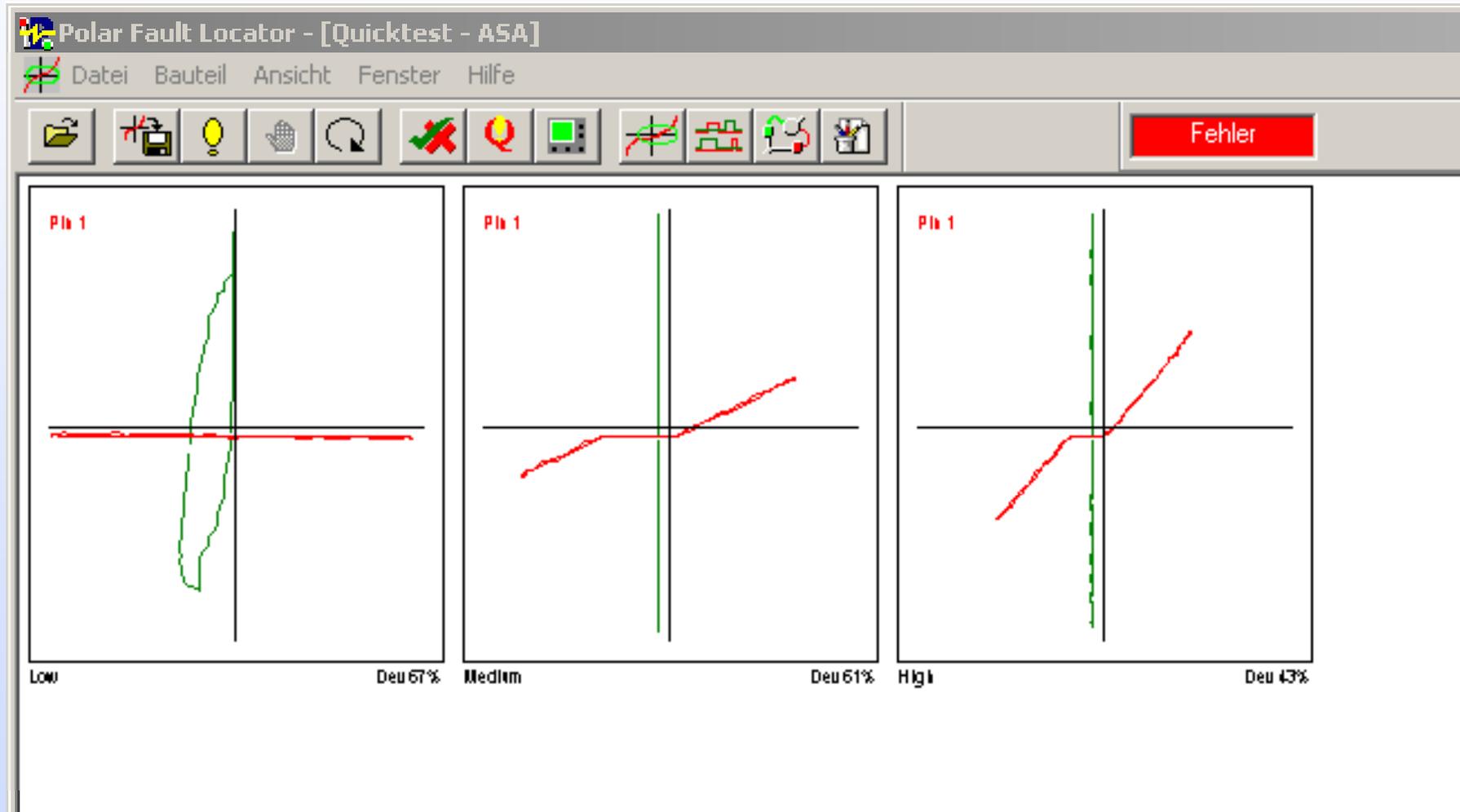
Pseudofehler durch Herstellerunterschiede



Typische Fehlerbilder

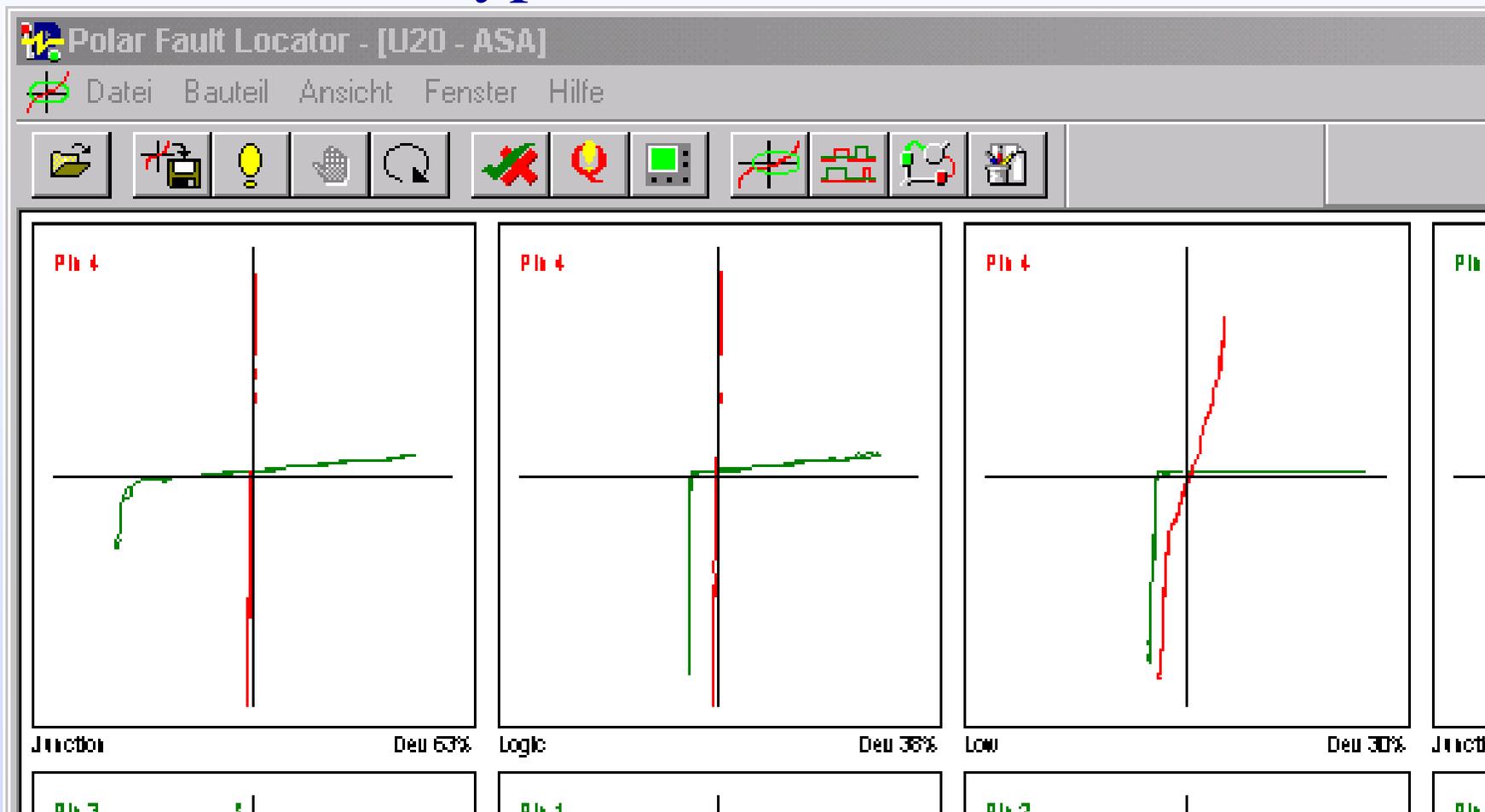


Typische Fehlerbilder



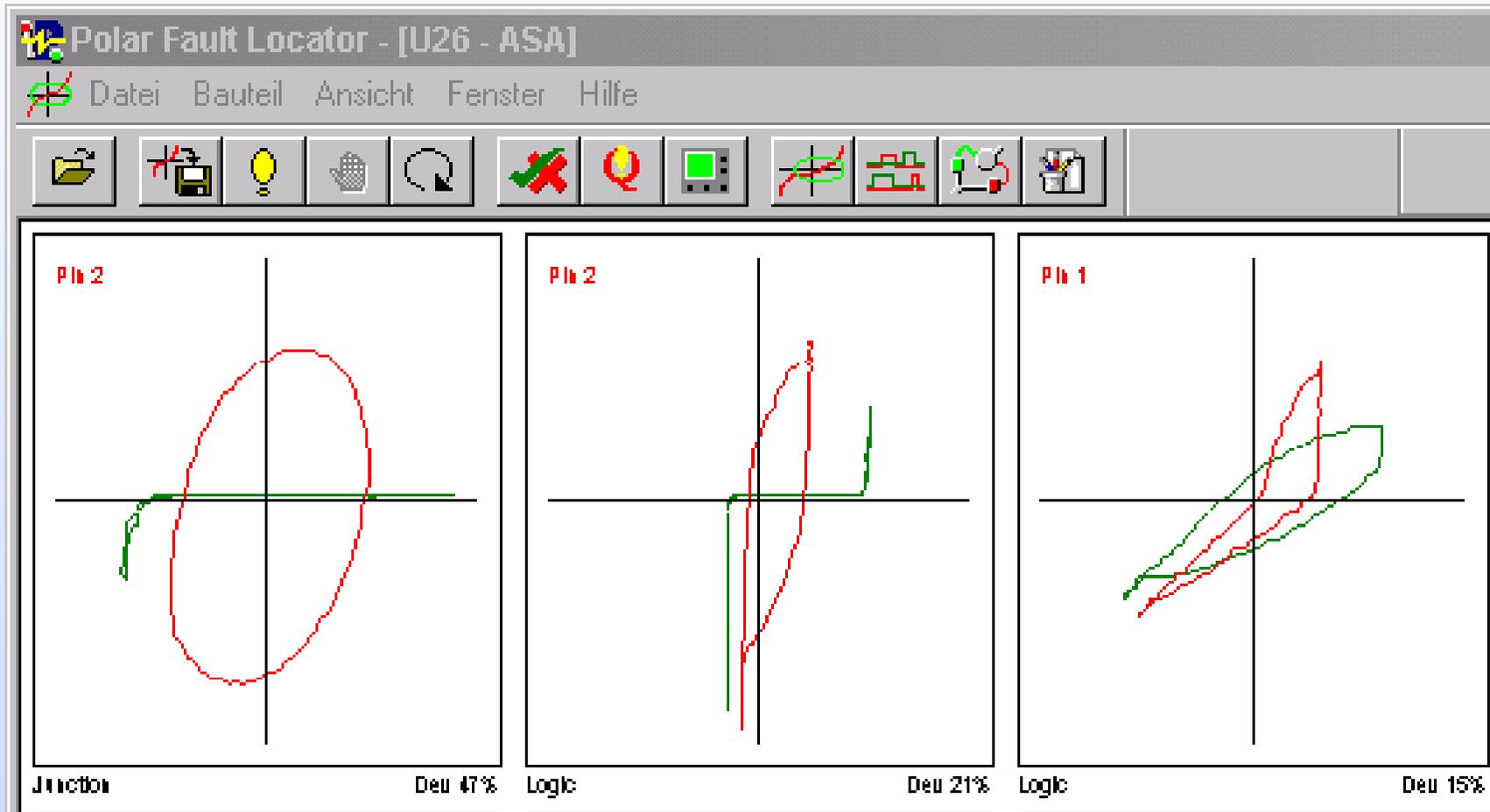
Widerstand nicht gelötet

Typische Fehlerbilder



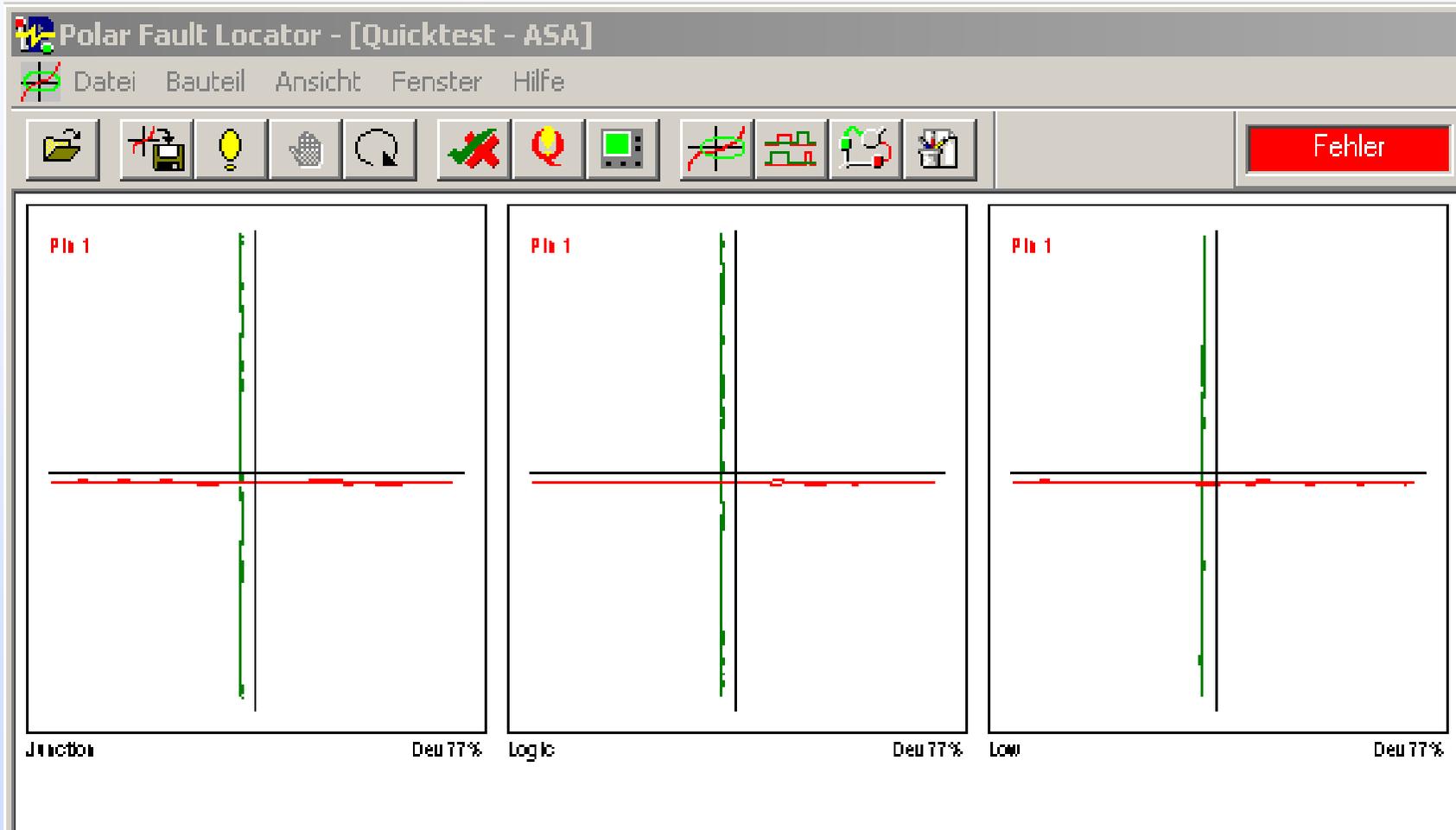
Masseschluss auf Pin 4

Typische Fehlerbilder



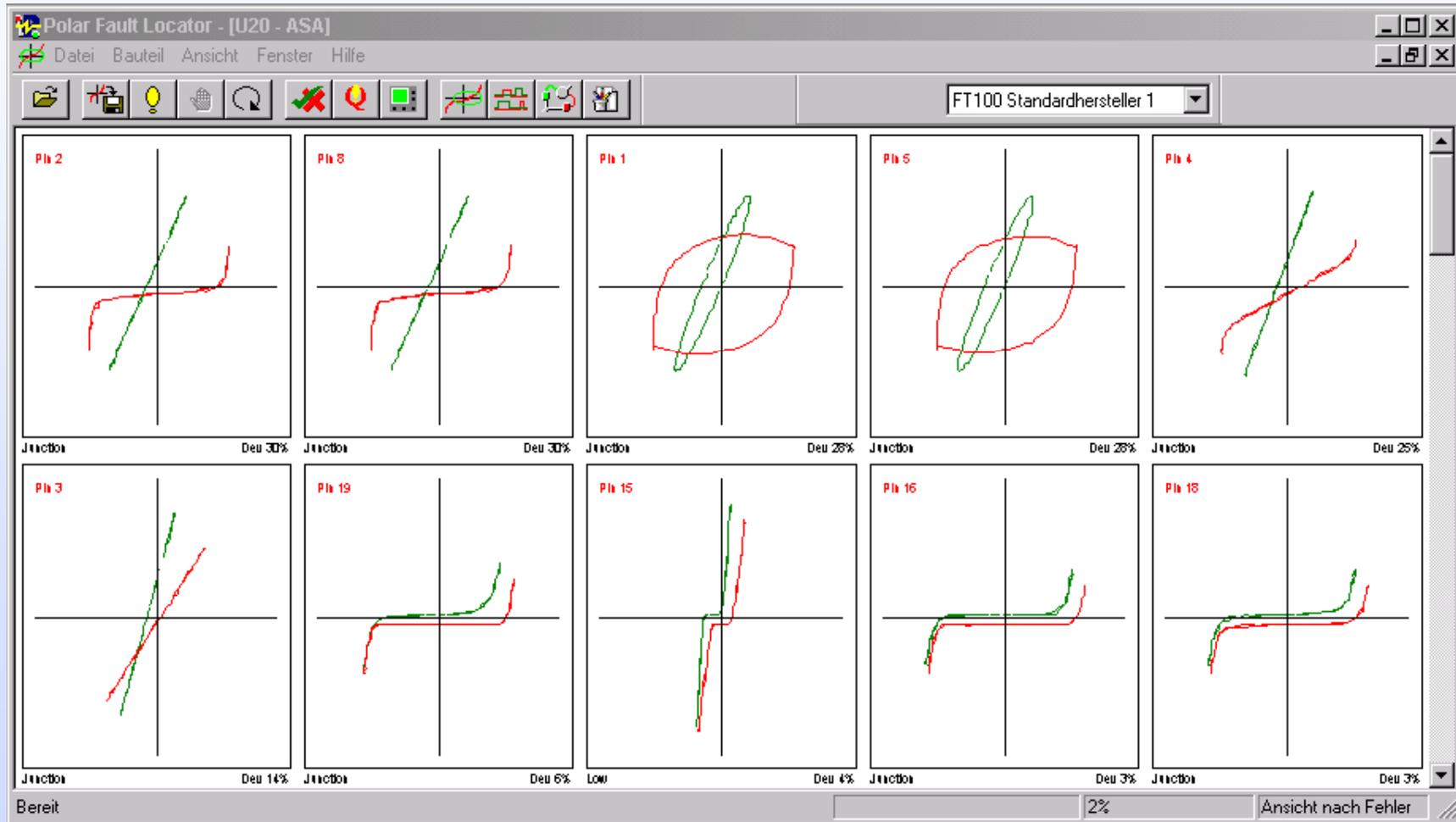
Defektes IC

Typische Fehlerbilder



Kondensator nicht gelötet

Typische Fehlerbilder

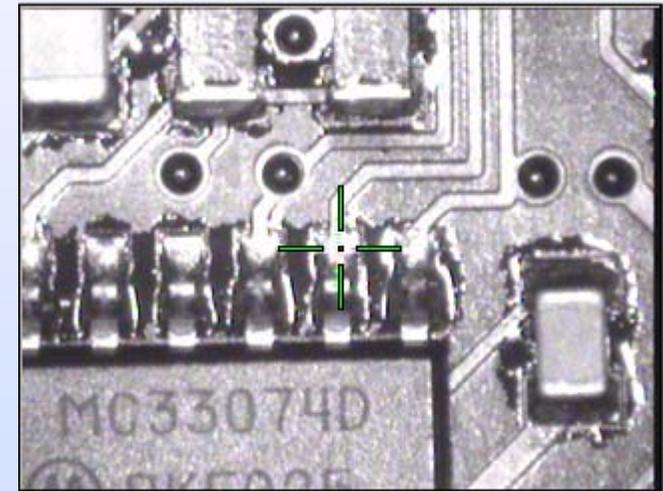


Mehrfache Fehler am IC

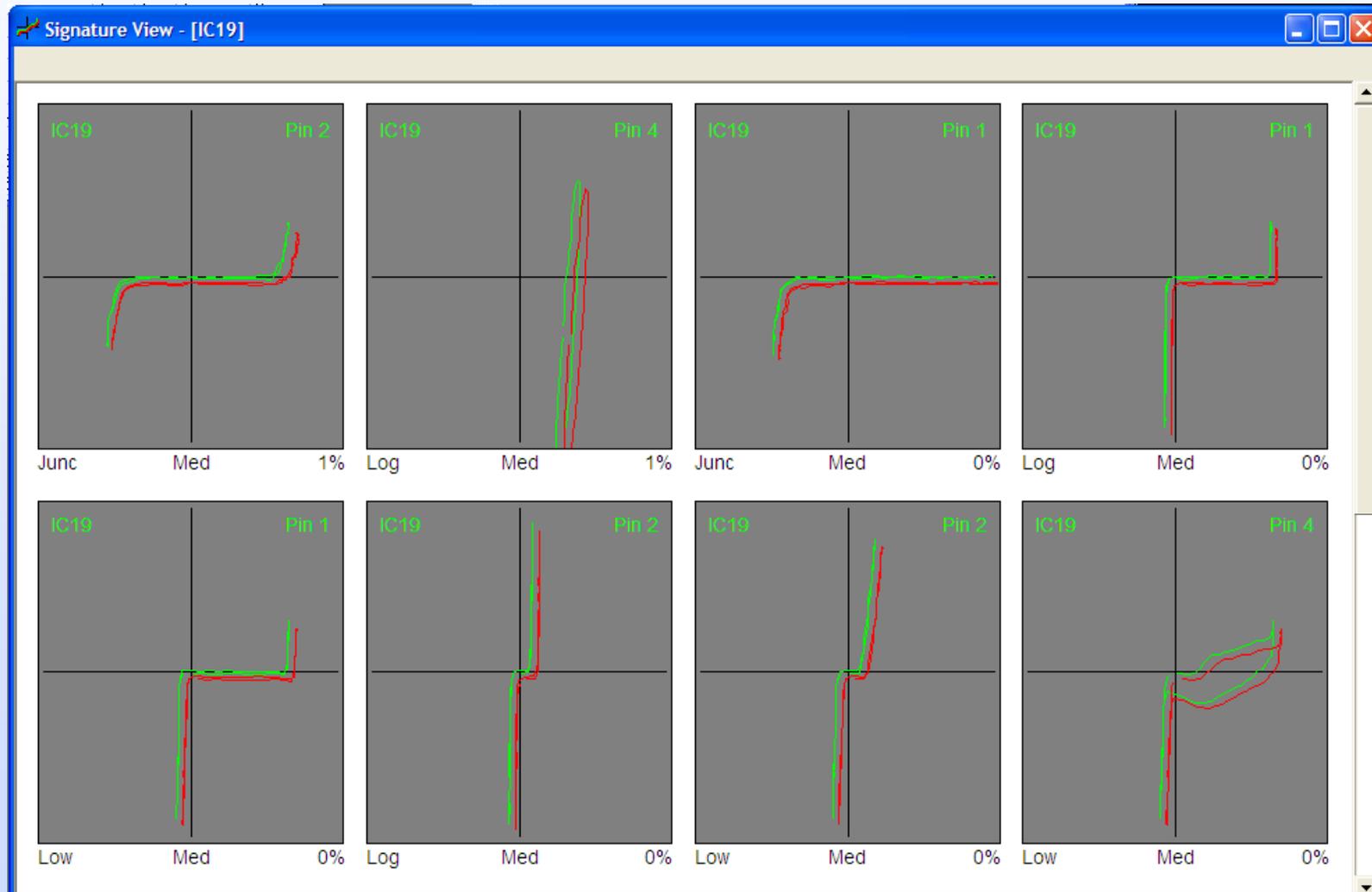
Prüfvoraussetzungen

- **Leiterplatte muß stromlos sein**
- **Schaltungsnetz muß an einer Stelle zugänglich sein**
- **Sämtliche Versorgungsspannungen und Bezugsmassen kurzschließen**
- **Keine Guarding-Techniken erforderlich**
- **Keine dedizierten Testpads erforderlich**
- **Evtl. Vorhandene Pufferbatterien abklemmen**

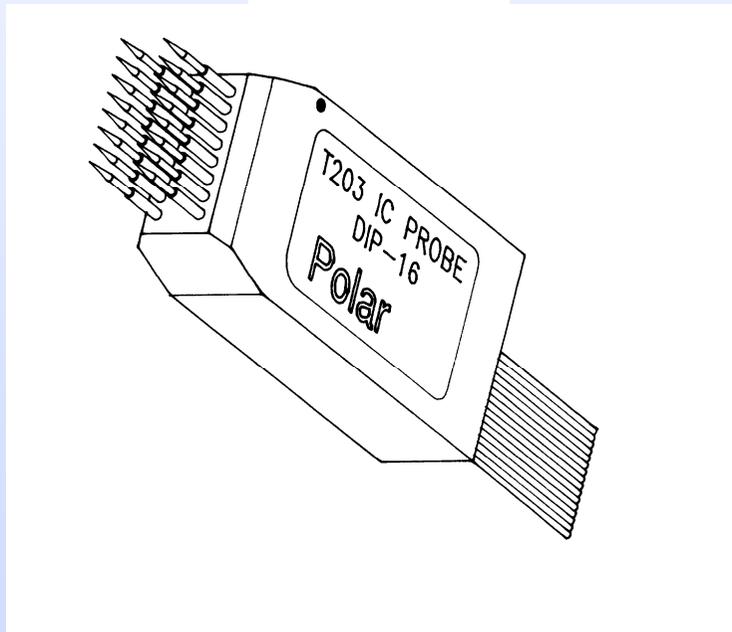
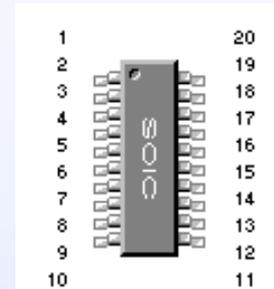
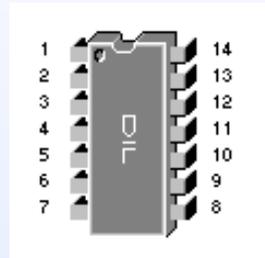
Echtzeitdarstellung



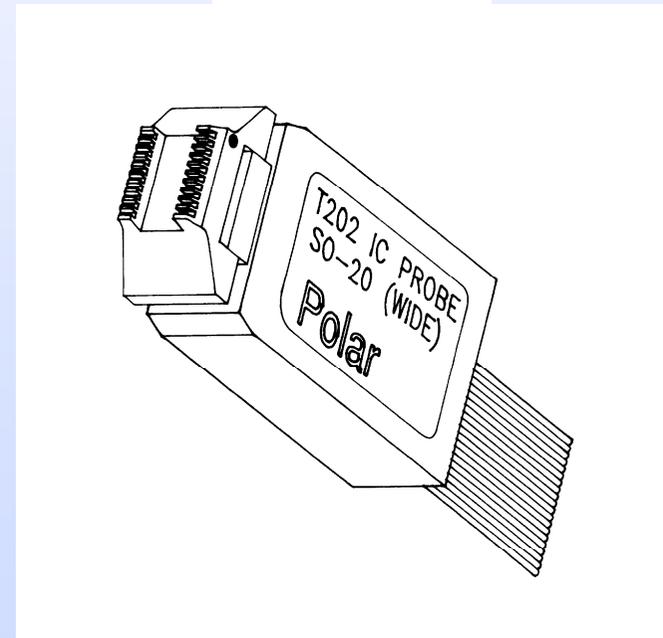
Der Speicherbetrieb



Kontaktiermethoden - Reparatur

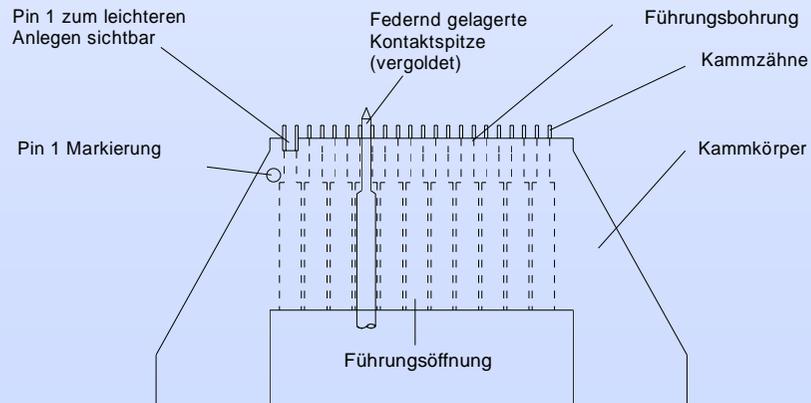
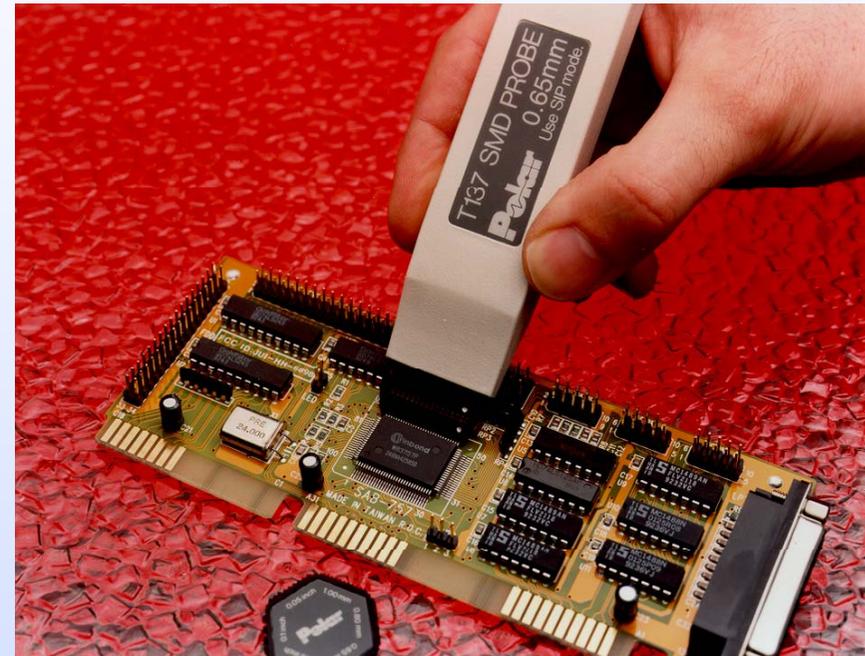
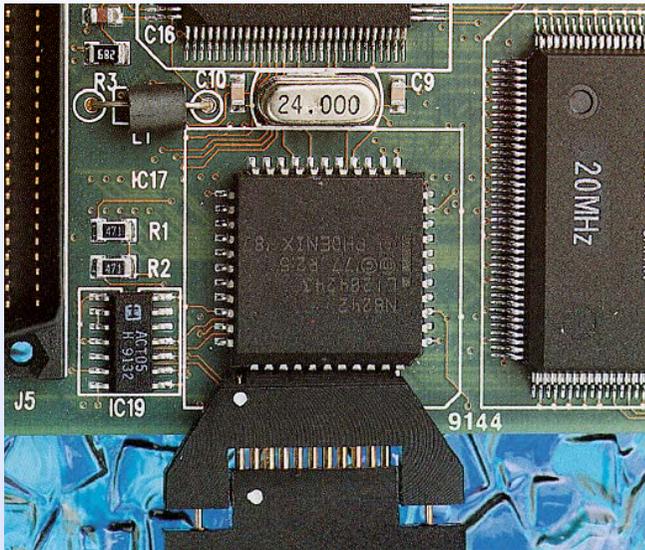


DIL- Prüfstempel

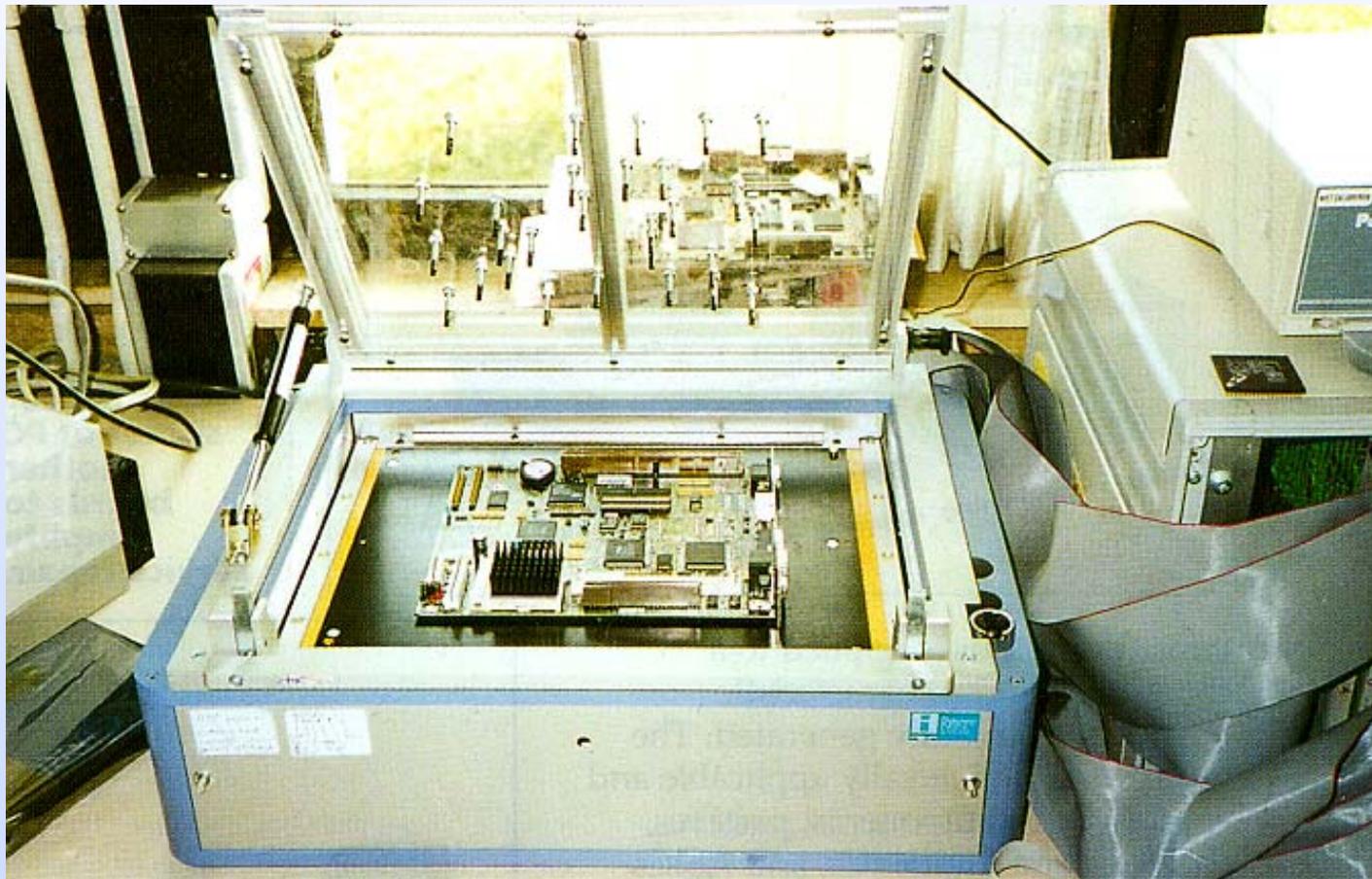


SOIC- Prüfstempel

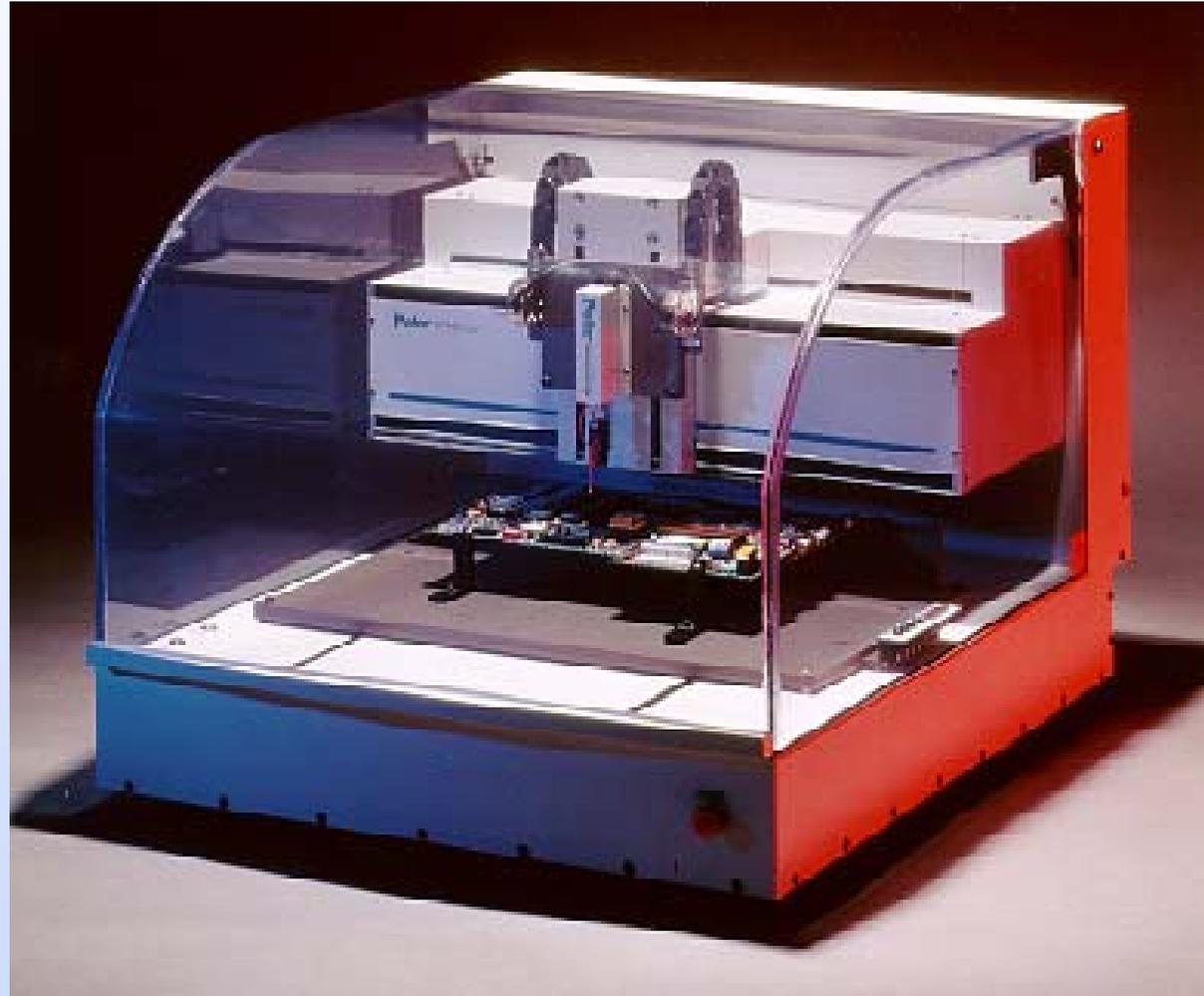
Kontaktiermethoden - Reparatur



Nadelbettadapter



GRS500 Flying Probe System



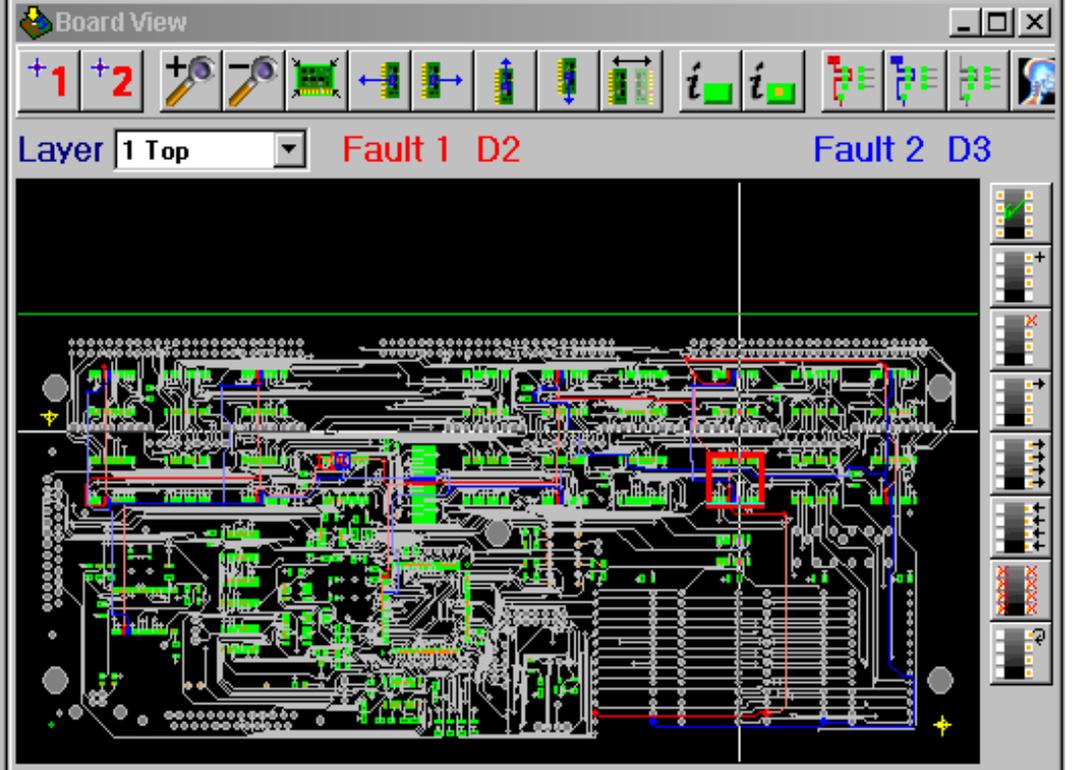
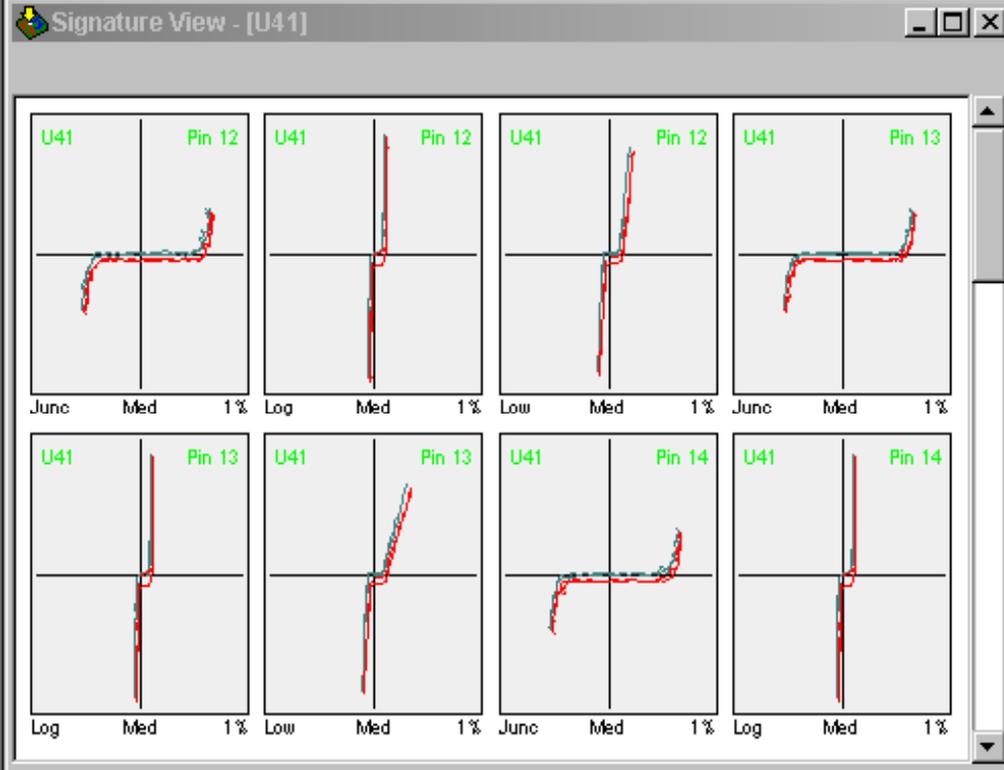
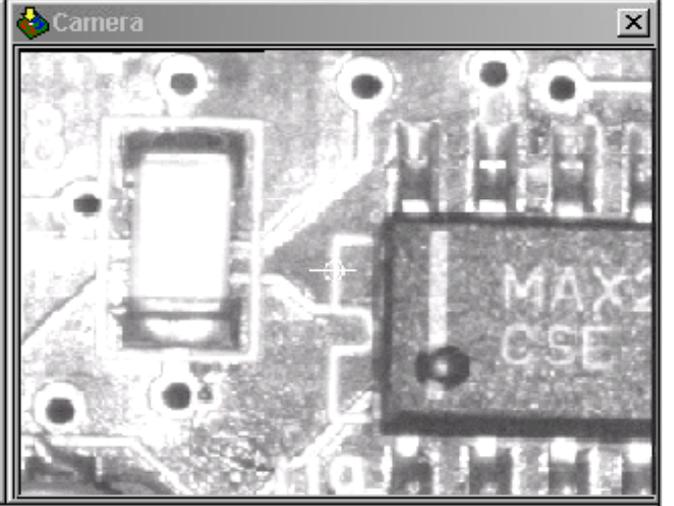
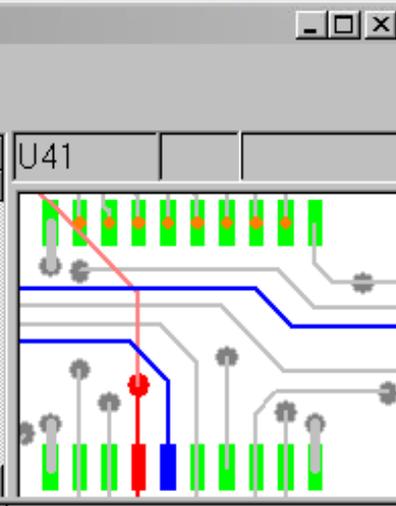
GRS500 Spezifikationen

- 1 Testnadel, welche exakt 90° aufsetzt
- 40 µm Positioniergenauigkeit, 16 µm Auflösung
- Max. 5 Messpunkte/Sekunde
- Boardgrösse max. 33 x 63 cm
- Abtastfläche 30 x 45 cm
- 10 cm Z-Achsenhub
- Einfache Programmierung durch Joystick/Kamera oder CAD-Datenübernahme
- Kontaktierung von Fine-Pitch IC's bis 0.4mm

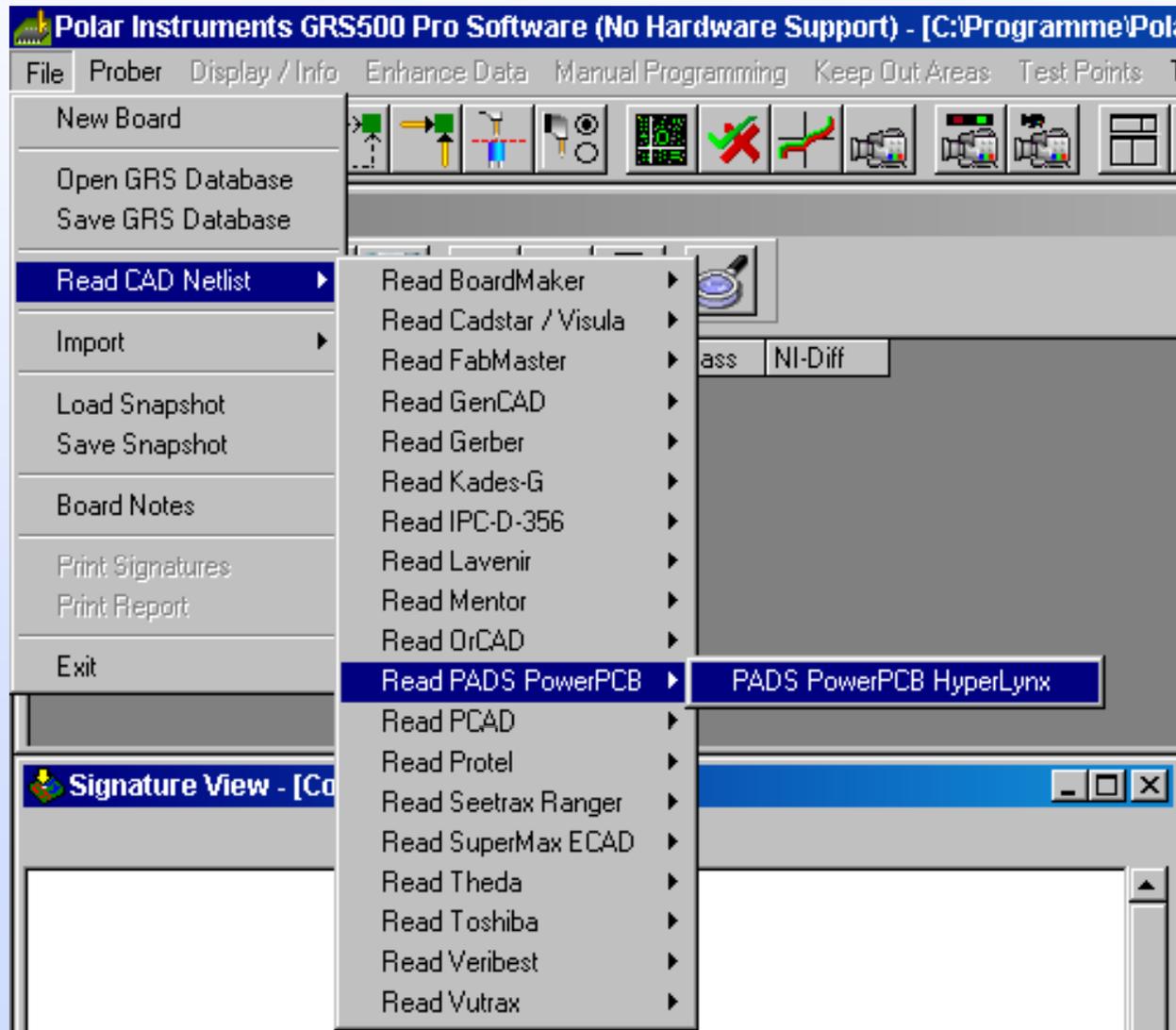


Test List

Component	Package	Pins	T/P	NI-Pass	NI-Diff
✓ C8		2	1	1	0
✓ R12		2	1	1	0
✓ R11		2	1	1	0
✓ U7		14	9	9	0
✓ R13		2	1	1	0
✓ U24		14	5	5	0
✓ U41		20	8	8	0
✓ U44		20	8	8	0
✓ U45		20	8	8	0
✓ U46		20	8	8	0



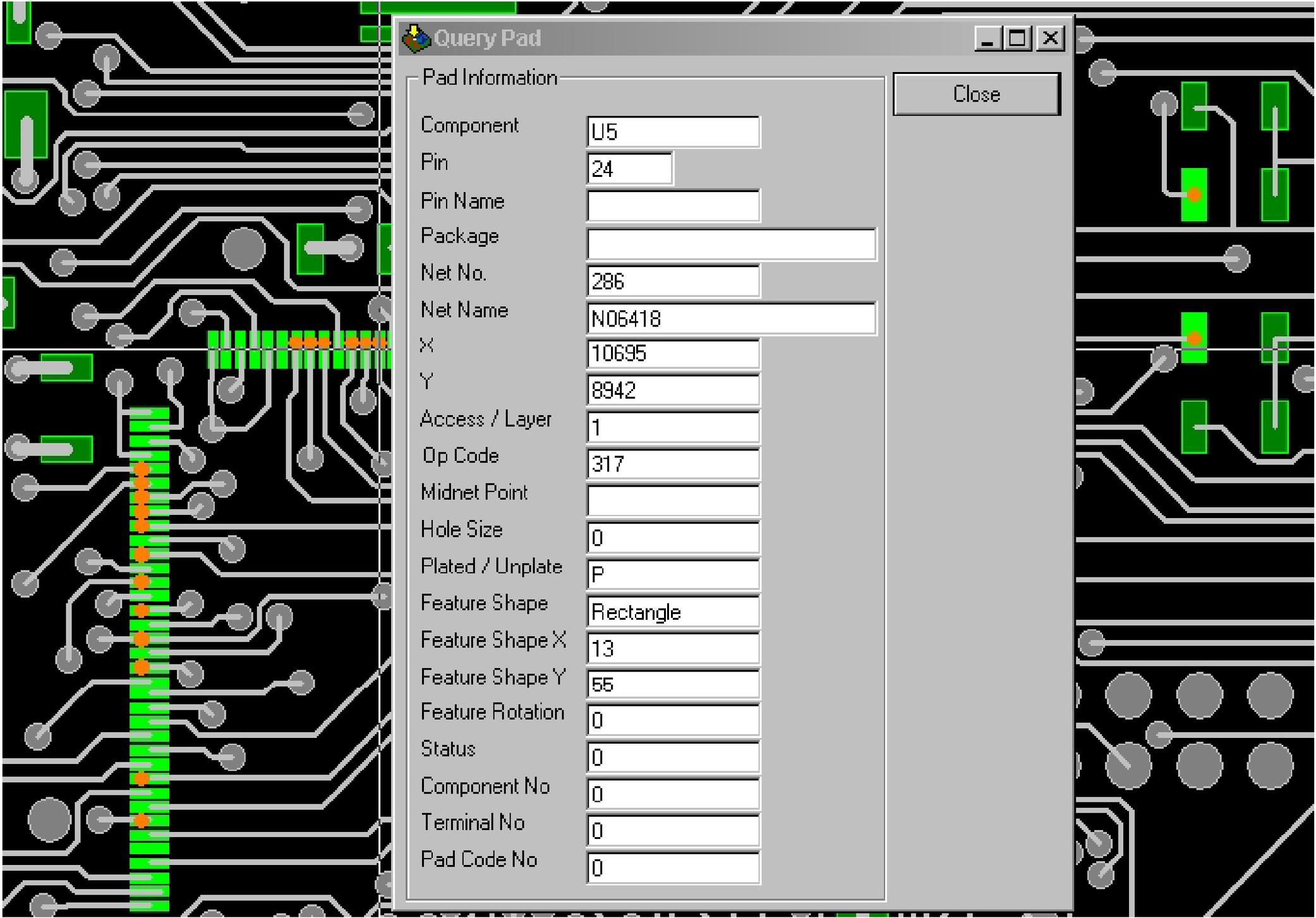
CAD-Import



Query Pad [Close]

Pad Information

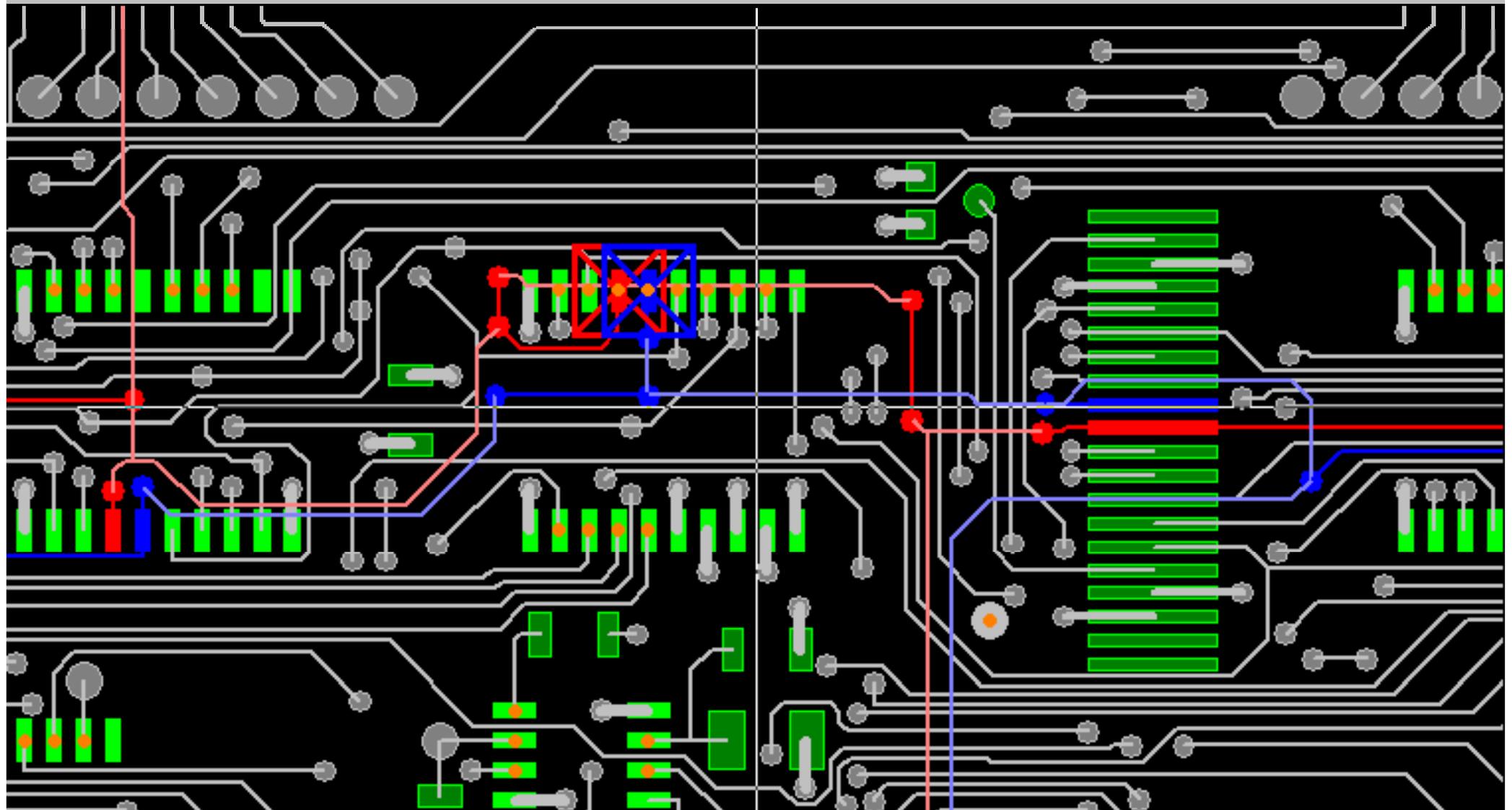
Component	U5
Pin	24
Pin Name	
Package	
Net No.	286
Net Name	N06418
X	10695
Y	8942
Access / Layer	1
Dp Code	317
Midnet Point	
Hole Size	0
Plated / Unplate	P
Feature Shape	Rectangle
Feature Shape X	13
Feature Shape Y	55
Feature Rotation	0
Status	0
Component No	0
Terminal No	0
Pad Code No	0

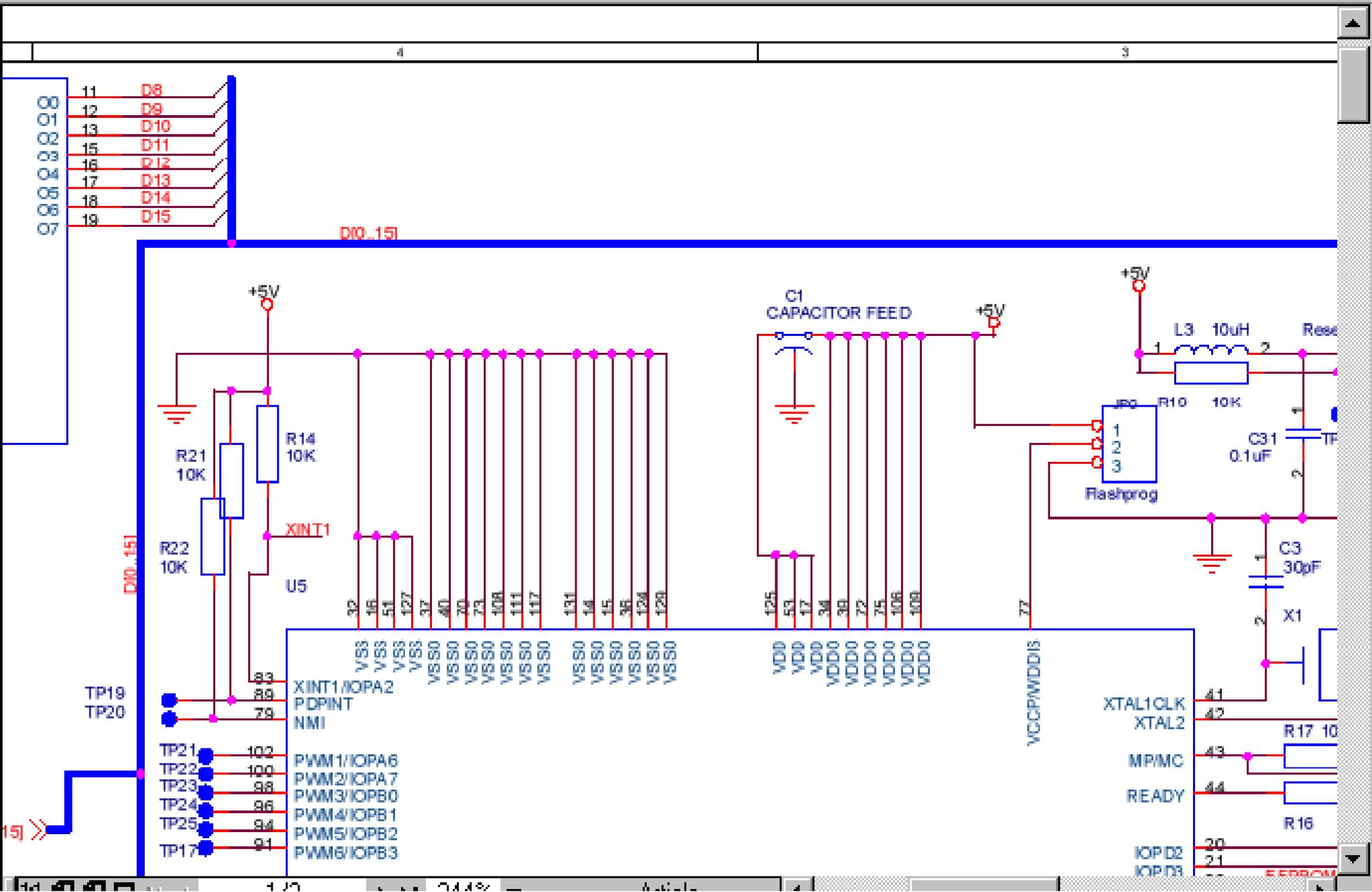


Layer 1 Top

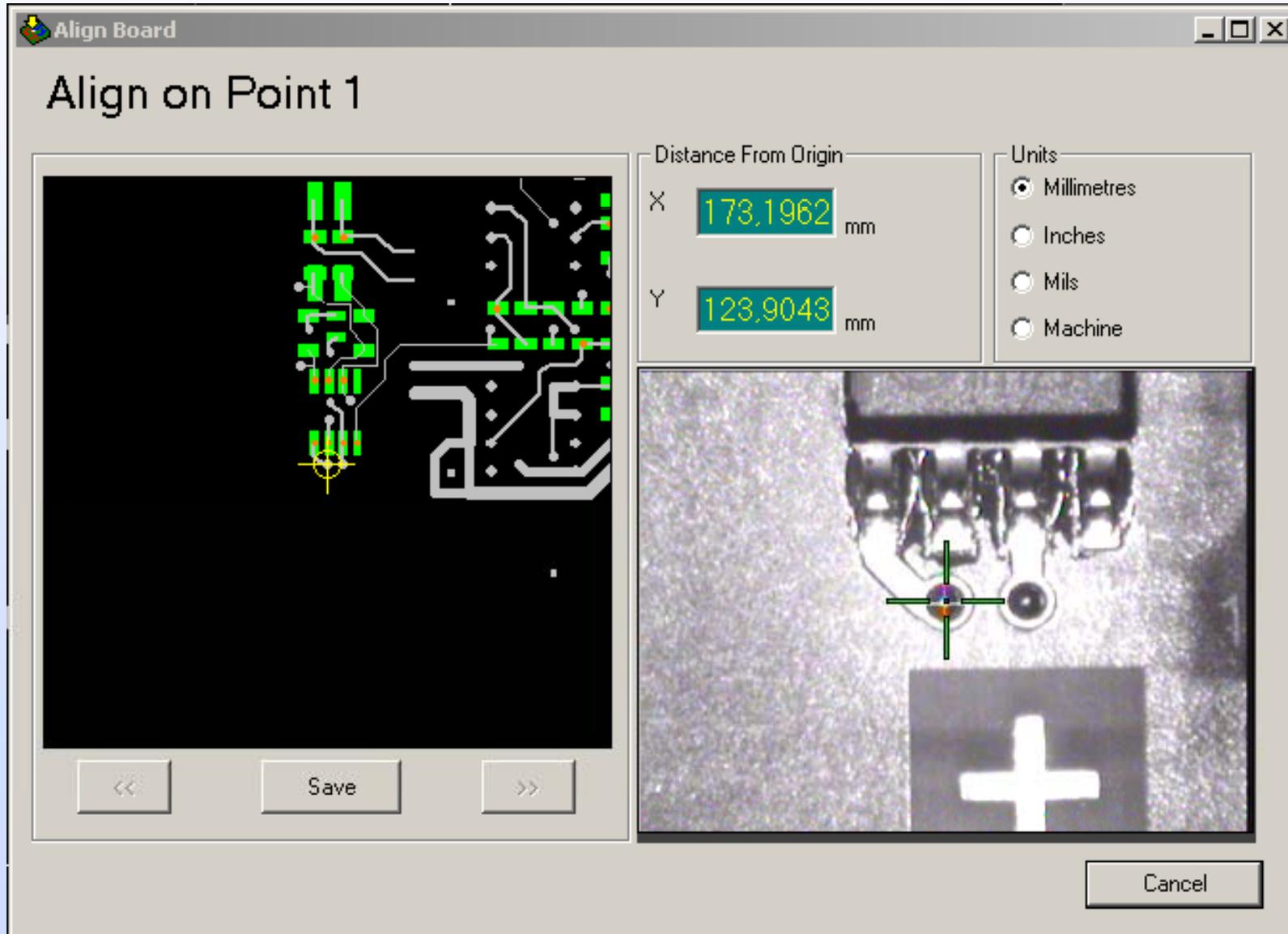
Fault 1 D2

Fault 2 D3





Baugruppenabgleich auf Referenzmarken

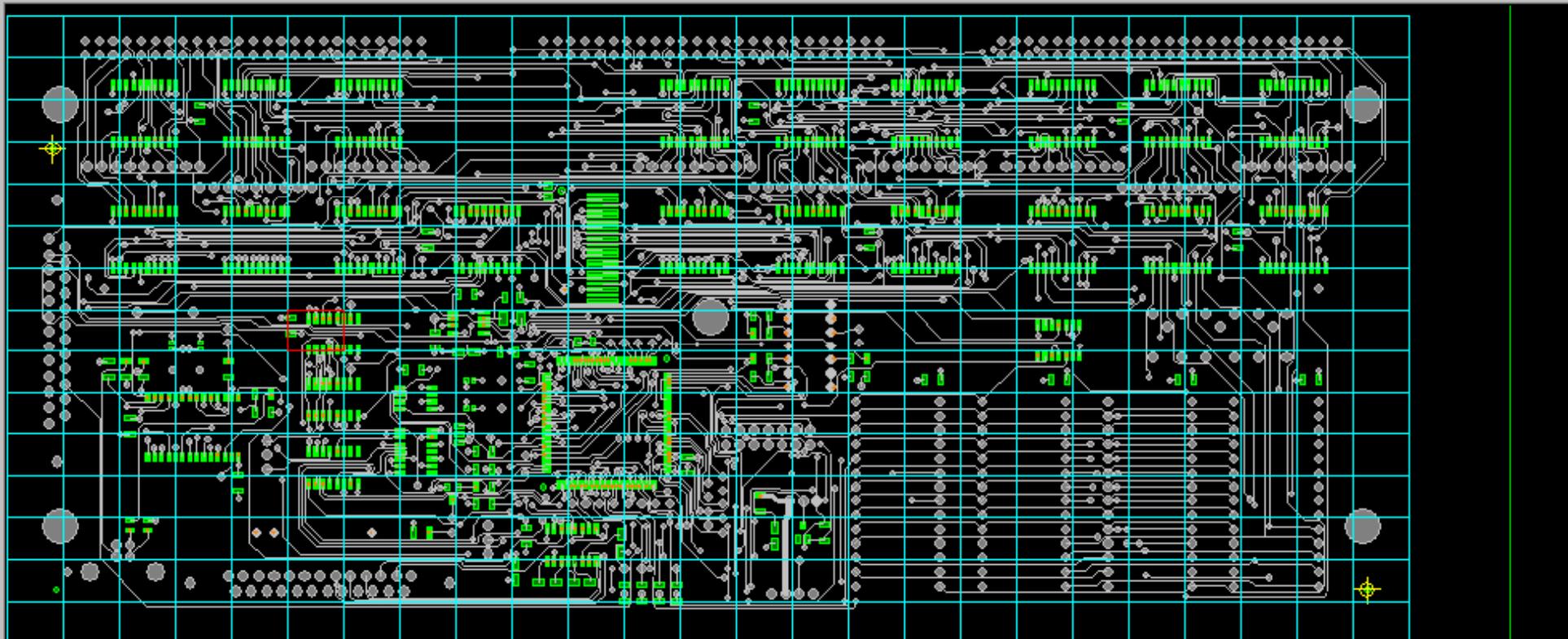


Manuelle Programmierung

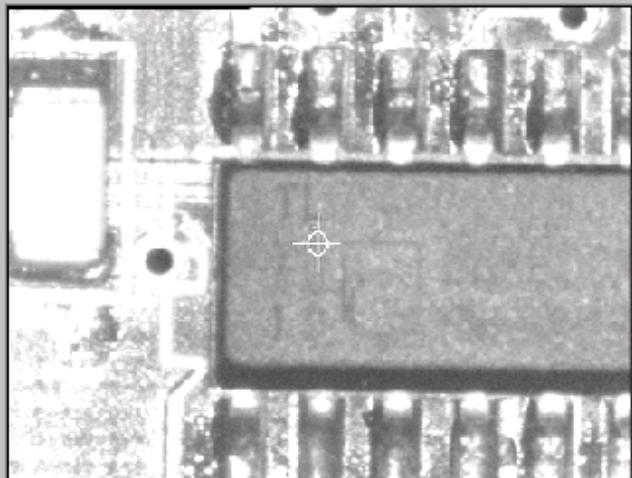
The screenshot shows the 'Manual Programming' window with the following fields and options:

- Component Information:**
 - Component Name: <NEW_COMPONENT>
 - Component Type: QFP
 - Package Description: QFP
 - Layer: 1
 - Shape: Round
- Pin Information:**
 - Pin Count: 32
 - QFP configuration: Pin1 Side: 8, Adj. Side: 8
 - Location of Pin 1: Corner, Middle
- Visual Representation:** A square pin array with 32 pins. Pin 1 is highlighted in red at the top-left corner. Other pins are green. Numbers 8, 9, 16, 17, 24, 25, and 32 are labeled on the pins.
- Buttons:** Rotate 90, Flip X, Flip Y, Apply >>, << Edit
- Distance From Origin:** X 0 mm
- Units:** Millimetres, Inches

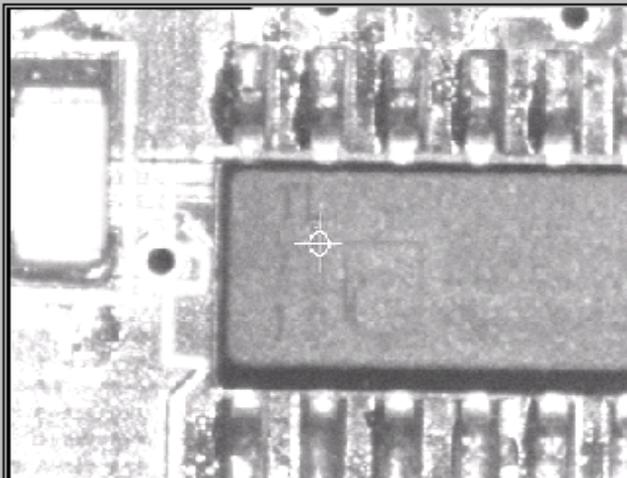
File Frames



Learnt View



Current View

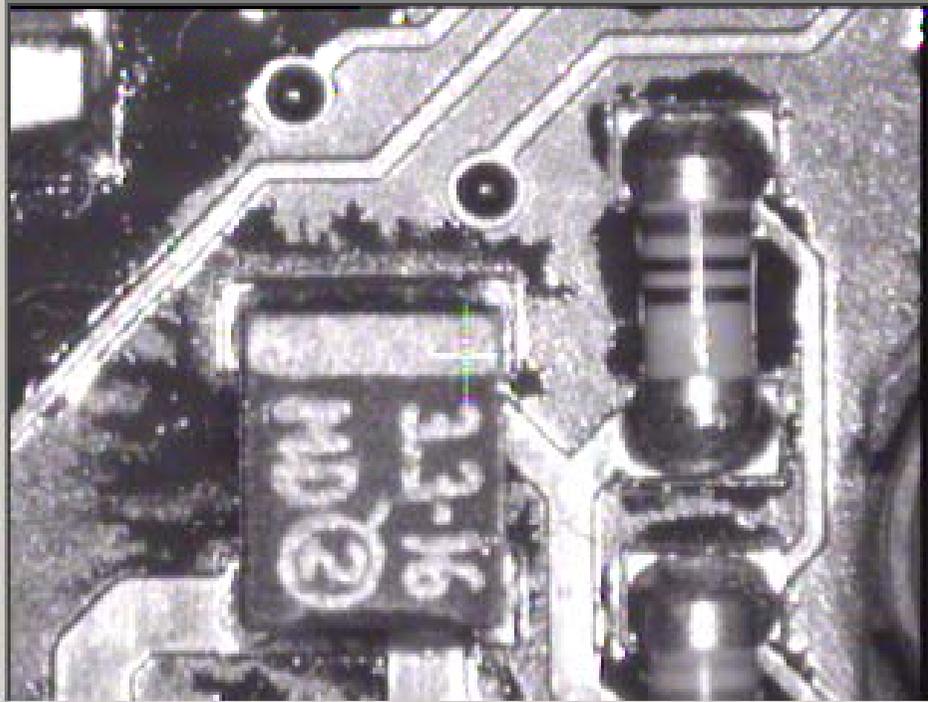


Close

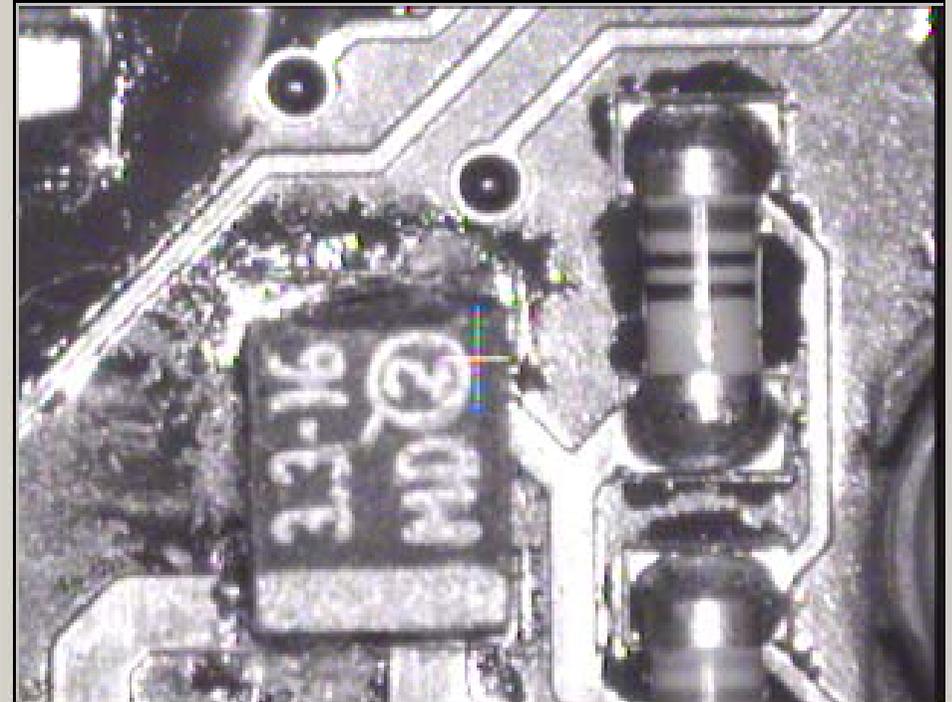
Notes (Enter Note before selecting Add Frame)

Verpolter Kondensator

Learn View

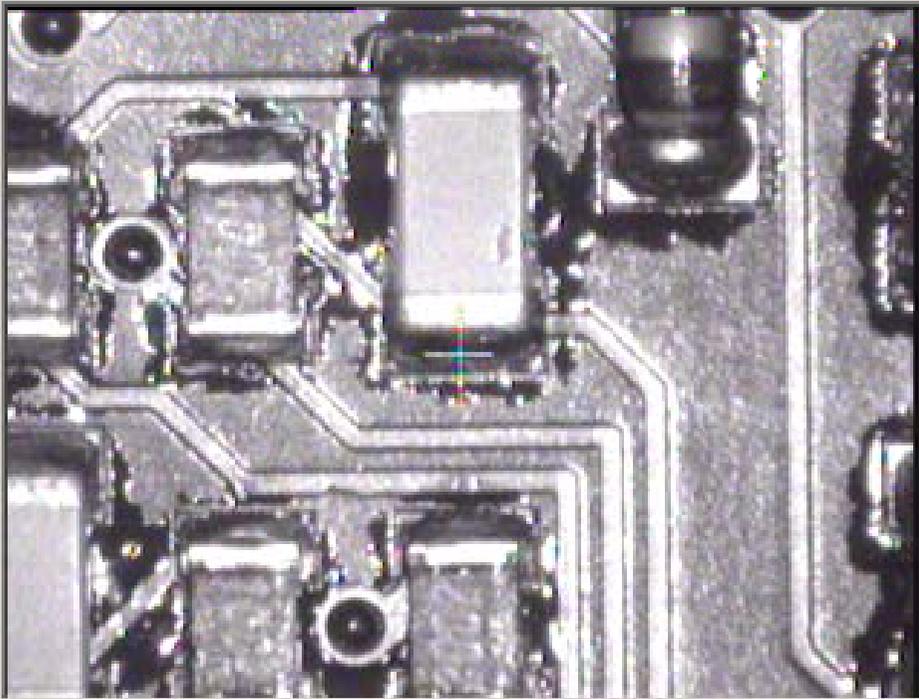


Current View

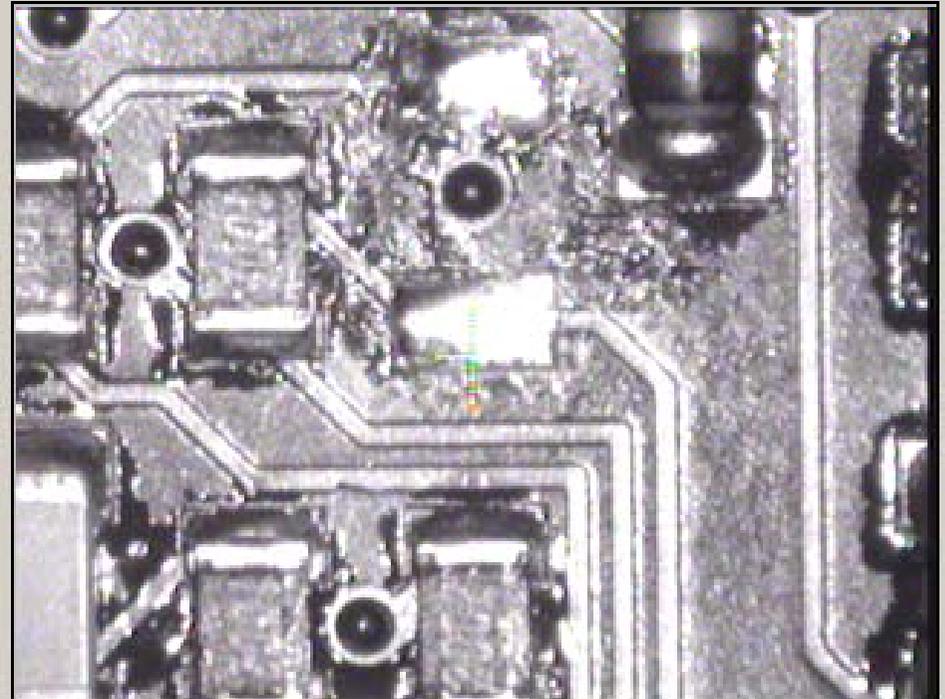


Fehlender Kondensator

Learnt View

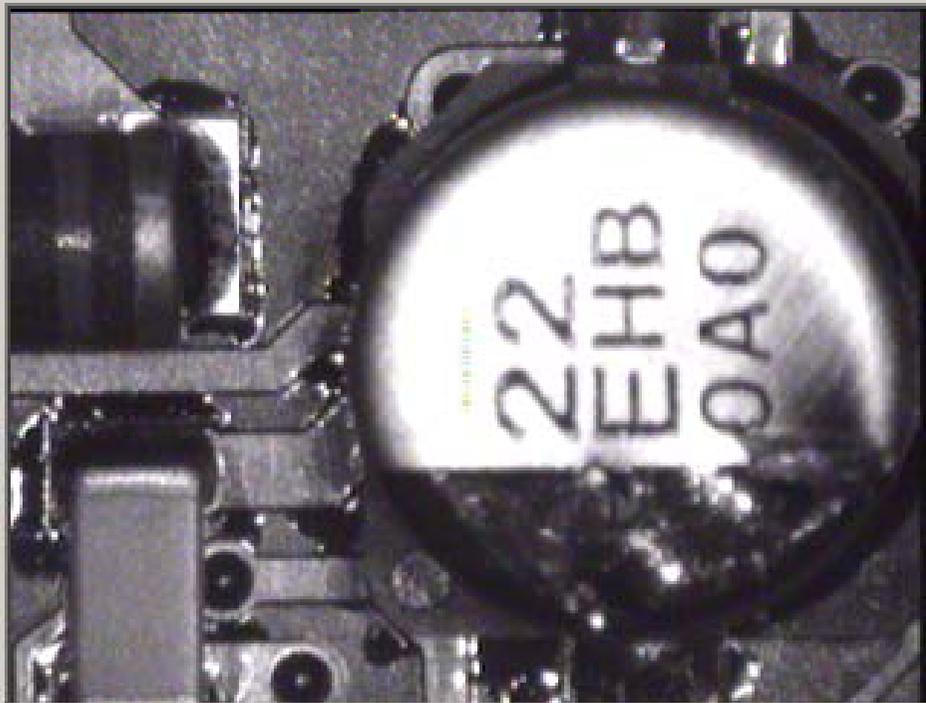


Current View

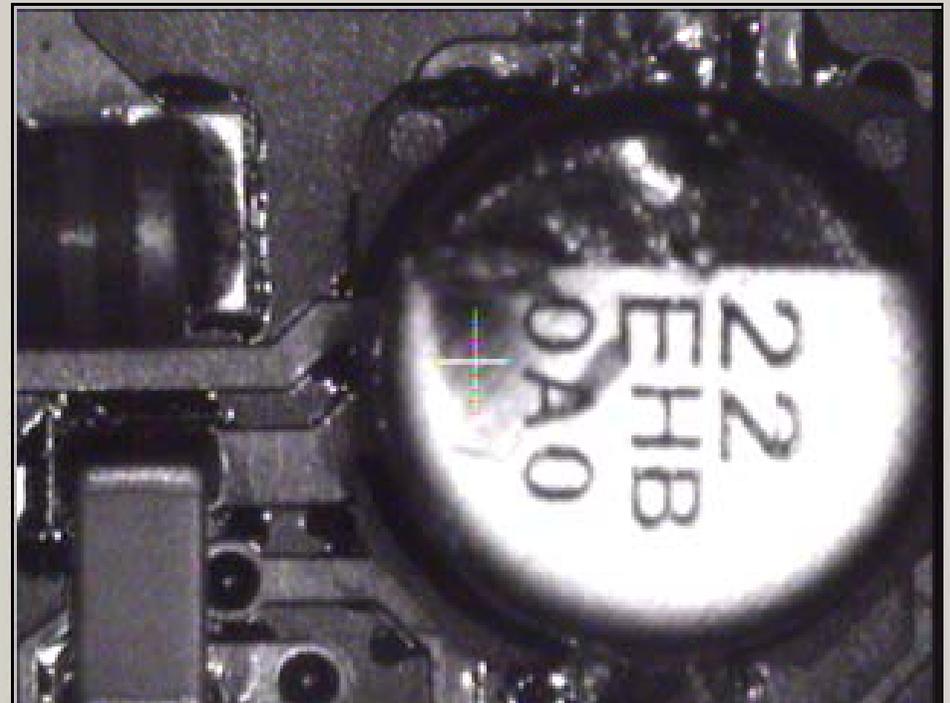


Verpolter Kondensator

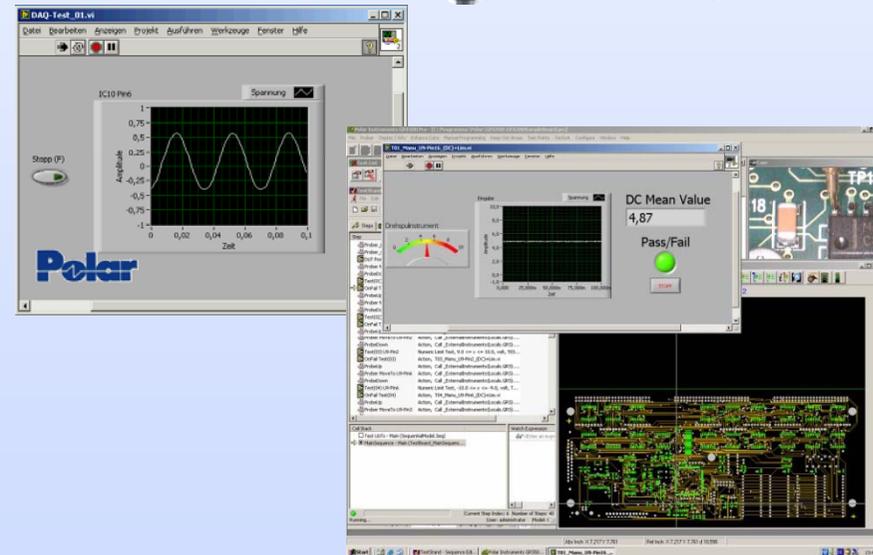
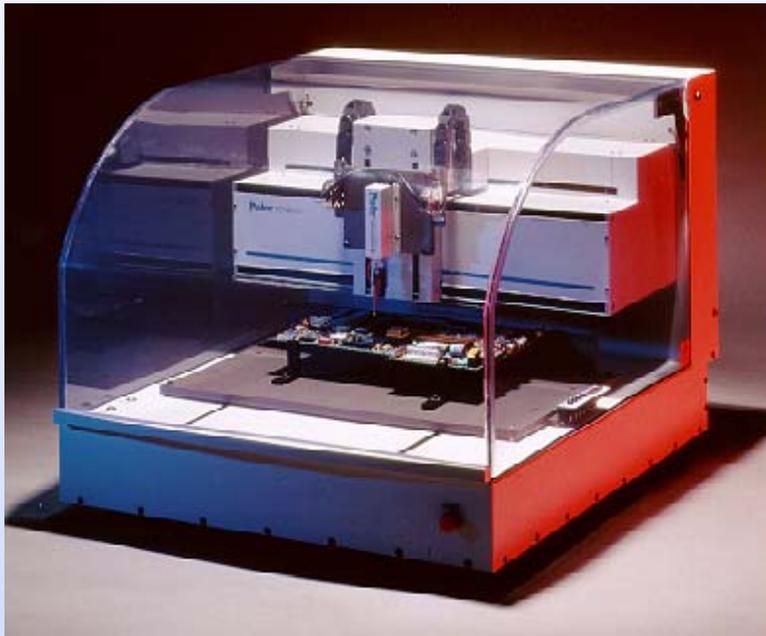
Learn View



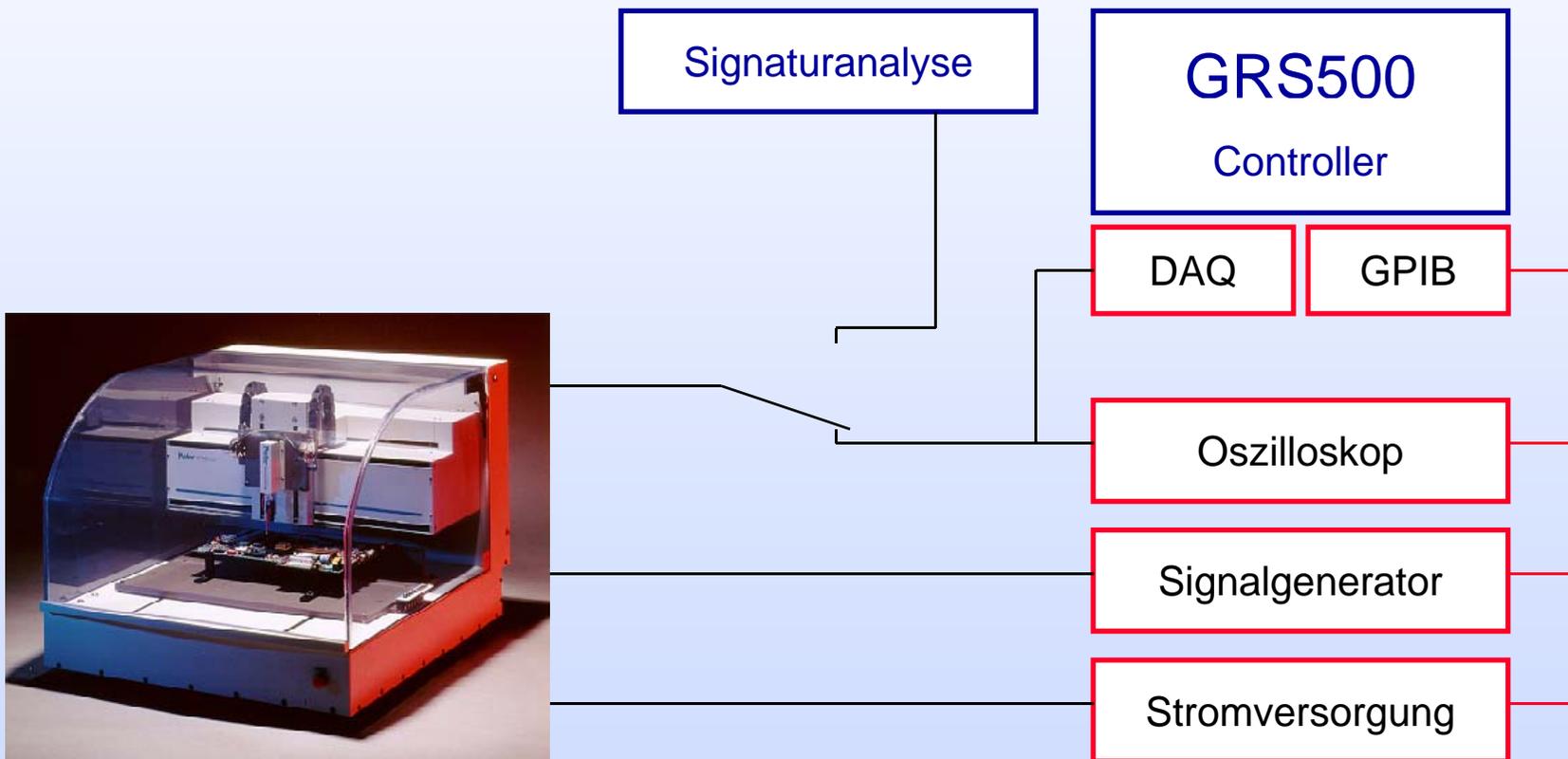
Current View



GRS500 ActiveTest Option



GRS500 ActiveTest Option

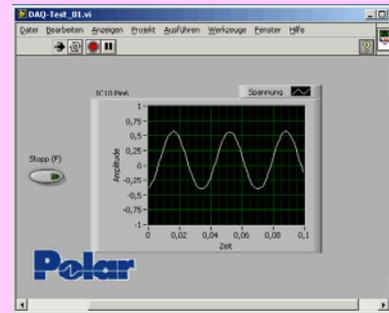


GRS500
Controller

GRS500
Software



National
Instruments
LabView



GPIB

USB

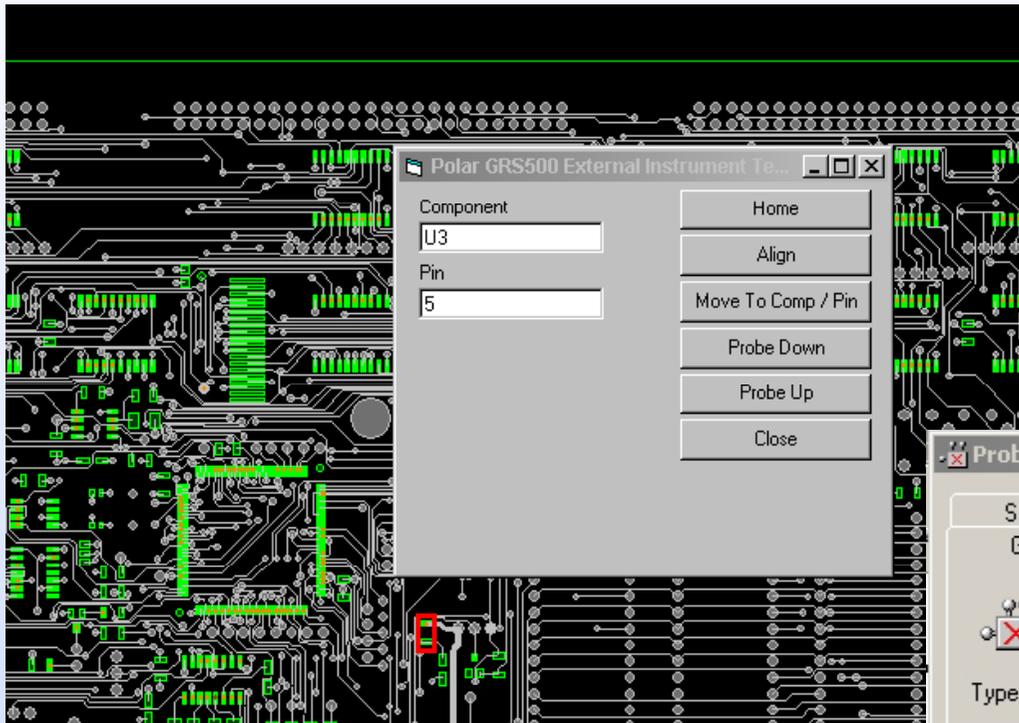
National
Instruments
TestStand

Step	Description	Flow Propertie
Prober_Home	Action, Create ExternalInstruments; Call_Ext...	
Prober_Common4_Only	Action, Call_ExternalInstruments(Locals:GRS)...	
DUT PowerOn	Action, T00_Auto_DUT_Power-ON.vi	
Prober MoveTo U9-Pin16	Action, Call_ExternalInstruments(Locals:GRS)...	
ProbeDown	Action, Call_ExternalInstruments(Locals:GRS)...	
Test(01) U9-Pin16	Numeric Limit Test, 4.5 <= x <= 5.5, V, T01_AU... Post Action	
OnFail Test(01)	Action, T01_Manu_U9-Pin16_(DC)+Lim.vi	
ProberUp	Action, Call_ExternalInstruments(Locals:GRS)...	
Prober MoveTo U7-Pin4	Action, Call_ExternalInstruments(Locals:GRS)...	
ProbeDown	Action, Call_ExternalInstruments(Locals:GRS)...	
Test(02) U7-Pin4	Numeric Limit Test, 4.5 <= x <= 5.5, volt, T02_... Post Action	

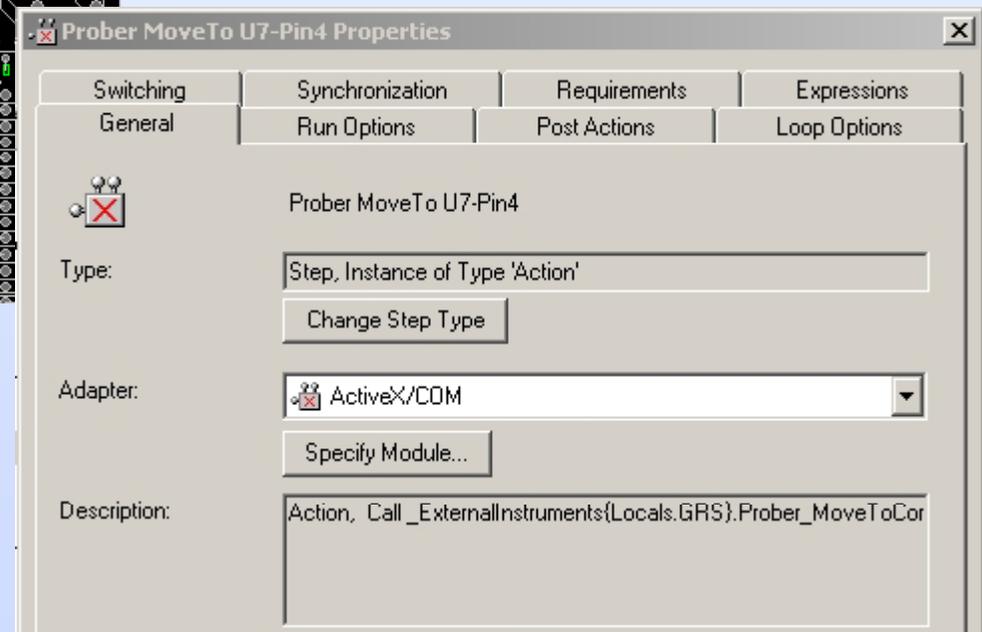
RS232

PCI

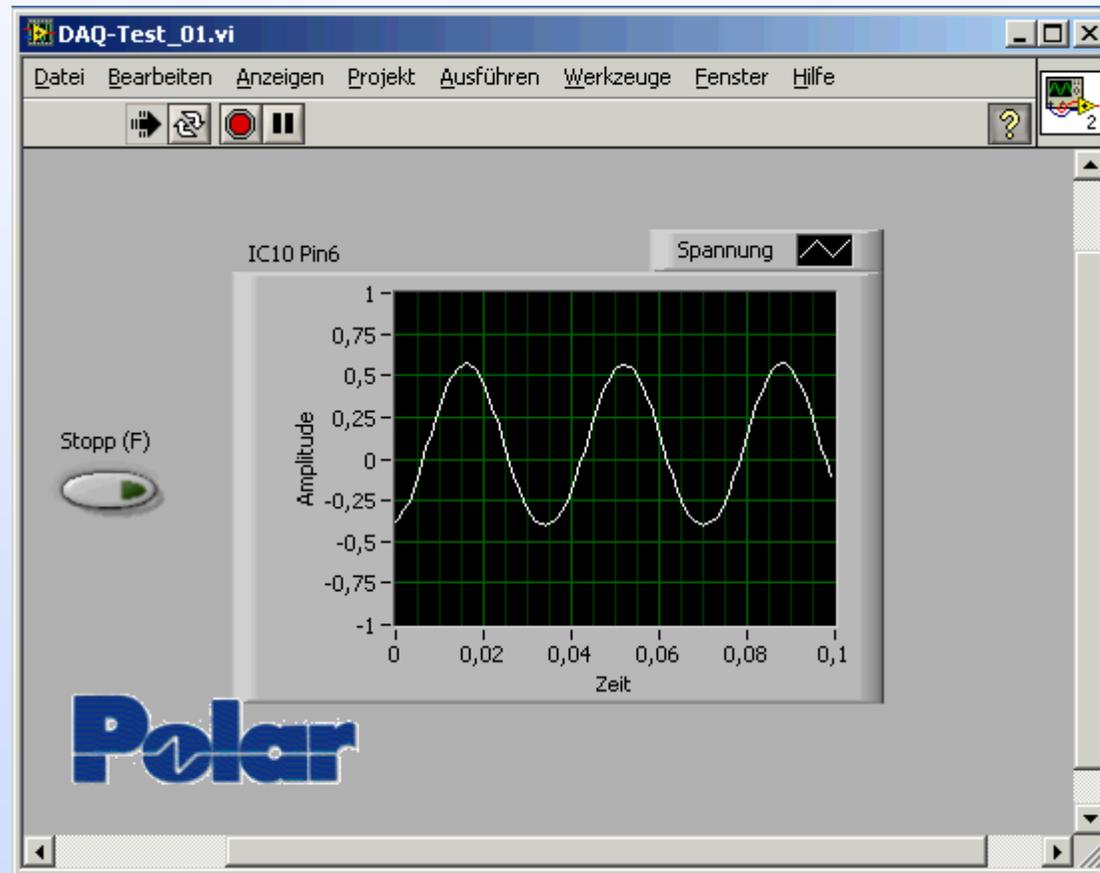
GRS500 External Instruments



NI TestStand



LabView



TestStand

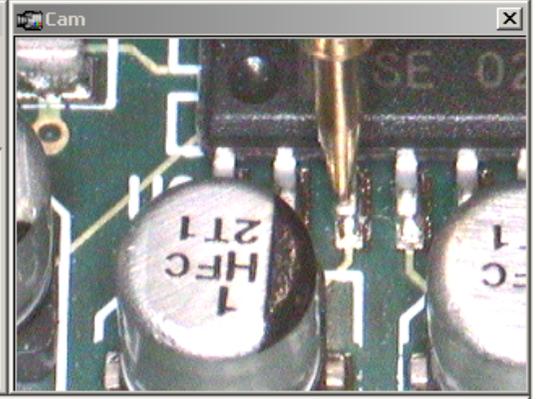
C:\... \National Instruments _ELECTRONICA-06 \TestStand \TestBoard_MainSequence.

Main | Setup | Cleanup | Parameters | Locals | View: MainSequence

Step	Description	Flow Properties
Prober_Home	Action, Create ExternalInstruments; Call _Exte...	
Prober_Common4_Only	Action, Call _ExternalInstruments{Locals.GRS}....	
DUT PowerOn	Action, T00_Auto_DUT_Power-ON.vi	
Prober MoveTo U9-Pin16	Action, Call _ExternalInstruments{Locals.GRS}....	
ProbeDown	Action, Call _ExternalInstruments{Locals.GRS}....	
Test(01) U9-Pin16	Numeric Limit Test, $4.5 \leq x \leq 5.5$, V, T01_Au...	Post Action
OnFail Test(01)	Action, T01_Manu_U9-Pin16_(DC)+Lim.vi	
ProbeUp	Action, Call _ExternalInstruments{Locals.GRS}....	
Prober MoveTo U7-Pin4	Action, Call _ExternalInstruments{Locals.GRS}....	
ProbeDown	Action, Call _ExternalInstruments{Locals.GRS}....	
Test(02) U7-Pin4	Numeric Limit Test, $4.5 \leq x \leq 5.5$, volt, T02_...	Post Action



Test List



TestStand - Sequence Editor [Running...] - [Test UUTs - TestBoard_Main...]

File Edit View Execute Debug Configure Tools Window Help

LabVIEW

Steps Context Report Threads: MainSequence - Main [TestBoard_MainSeque...

Step	Description	Status
Prober MoveTo U9-Pin2	Action, Call _ExternalInstruments{Locals.GRS}...	Done
ProbeDown	Action, Call _ExternalInstruments{Locals.GRS}...	Done
Test(03) U9-Pin2	{9.4}, Numeric Limit Test, 9.0 <= x <= 10.0, v...	Passed
OnFail Test(03)	Action, T03_Man_u9-Pin2 (DC)+Lim.vi	
ProbeUp	Action, Call _ExternalI	
Prober MoveTo U9-Pin6	Action, Call _ExternalI	
ProbeDown	Action, Call _ExternalI	
Test(04) U9-Pin6	{-9.2}, Numeric Limit Te	
OnFail Test(04)	Action, T04_Man_u9-	
ProbeUp	Action, Call _ExternalI	
Prober MoveTo U9-Pin3	Action, Call _ExternalI	
ProbeDown	Action, Call _ExternalI	
Test(05) U9-Pin3	{3.2}, Numeric Limit Te	
OnFail Test(05)	Action, T05_Man_u9-	
ProbeUp	Action, Call _ExternalI	
Prober MoveTo U5-Pin82	Action, Call _ExternalI	
ProbeDown	Action, Call _ExternalI	
Test(06) U5-Pin82	Pass/Fail Test, T06_Au	
OnFail Test(06)	Action, T06_Man_u5-	
ProbeUp	Action, Call _ExternalI	
Prober MoveTo U9-Pin3	Action, Call _ExternalI	
ProbeDown	Action, Call _ExternalI	
Test(07) U5-Pin93	Pass/Fail Test, T07_Au	
OnFail_Test(07)	Action, T07_Man_u5-	

Call Stack

- Test UUTs - Main (SequentialModel.Seq)
- MainSequence - Main (TestBoard_MainSequenc...

Componen Package

Board View

T07_Man_u5-Pin93_(FDom)+Lim.vi

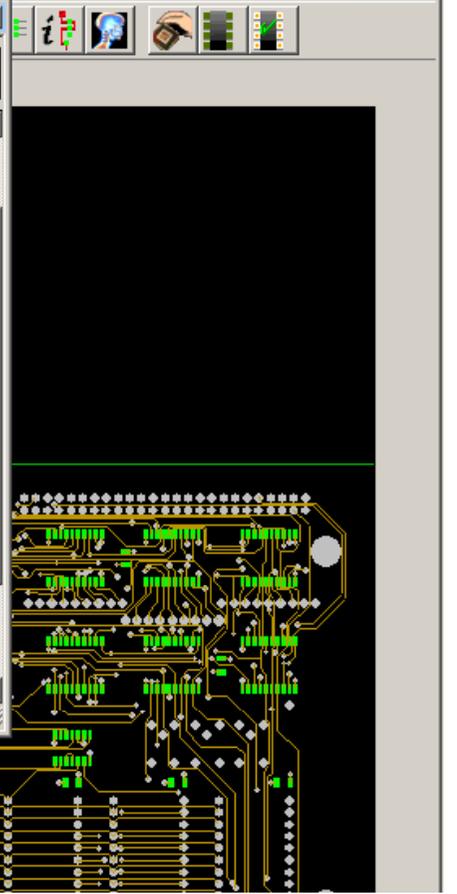
Datei Bearbeiten Anzeigen Projekt Ausführen Werkzeuge Fenster Hilfe

Eingabe Spannung

Result Spannung (FFT - (Spitze))

Pass/Fail

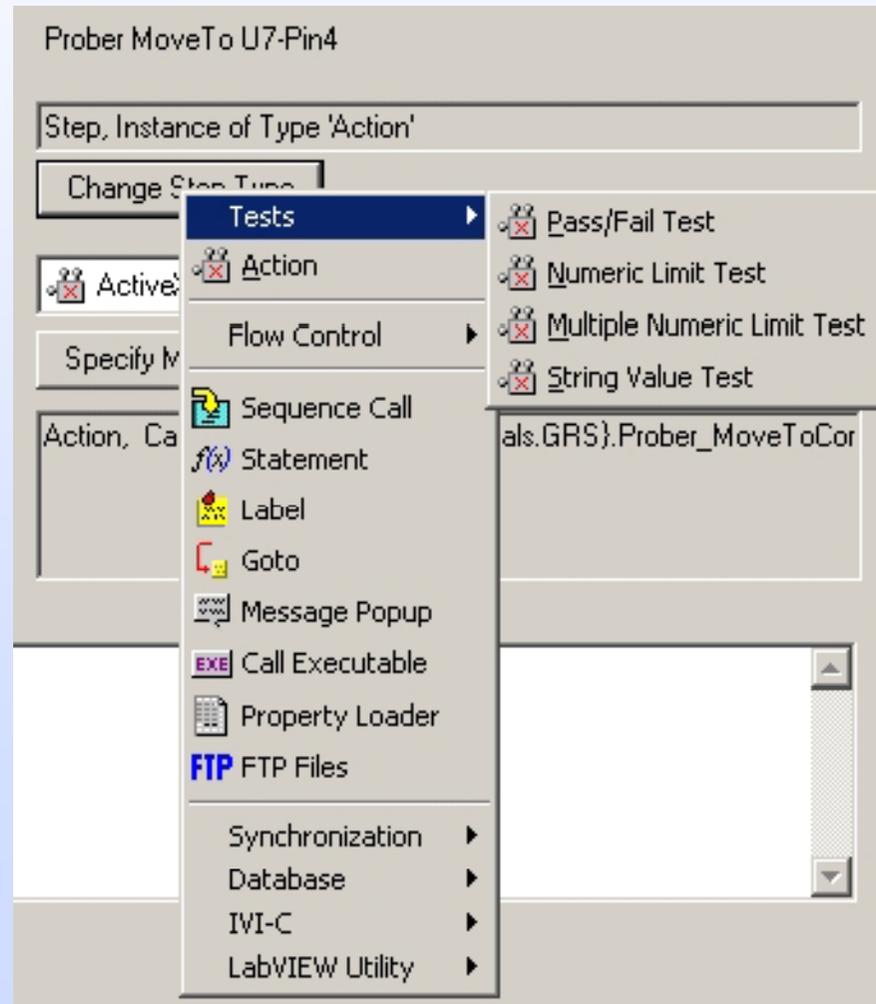
STOPP



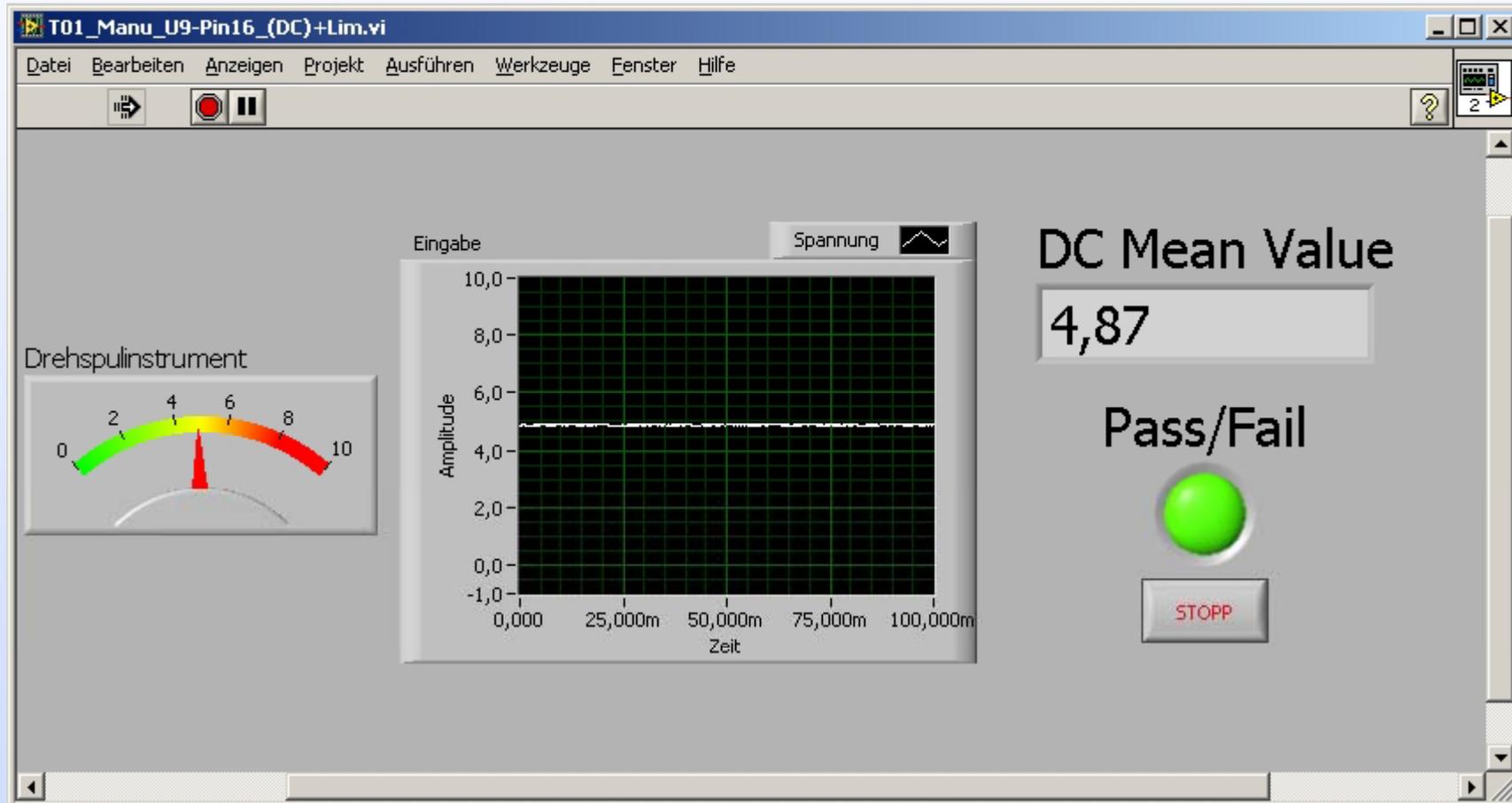
ActiveTest

- DC-Messung
- AC-Messung
- Kurvenformverlauf
- Toleranzlimits, Gut/Schlecht-Vergleich
- FFT Spektrumanalyse
- Signalgenerator
- Digital I/O Ports zur Steuerung des Messobjekts
- Einbindung von weiteren Geräten via GPIB, RS232, USB, PCI

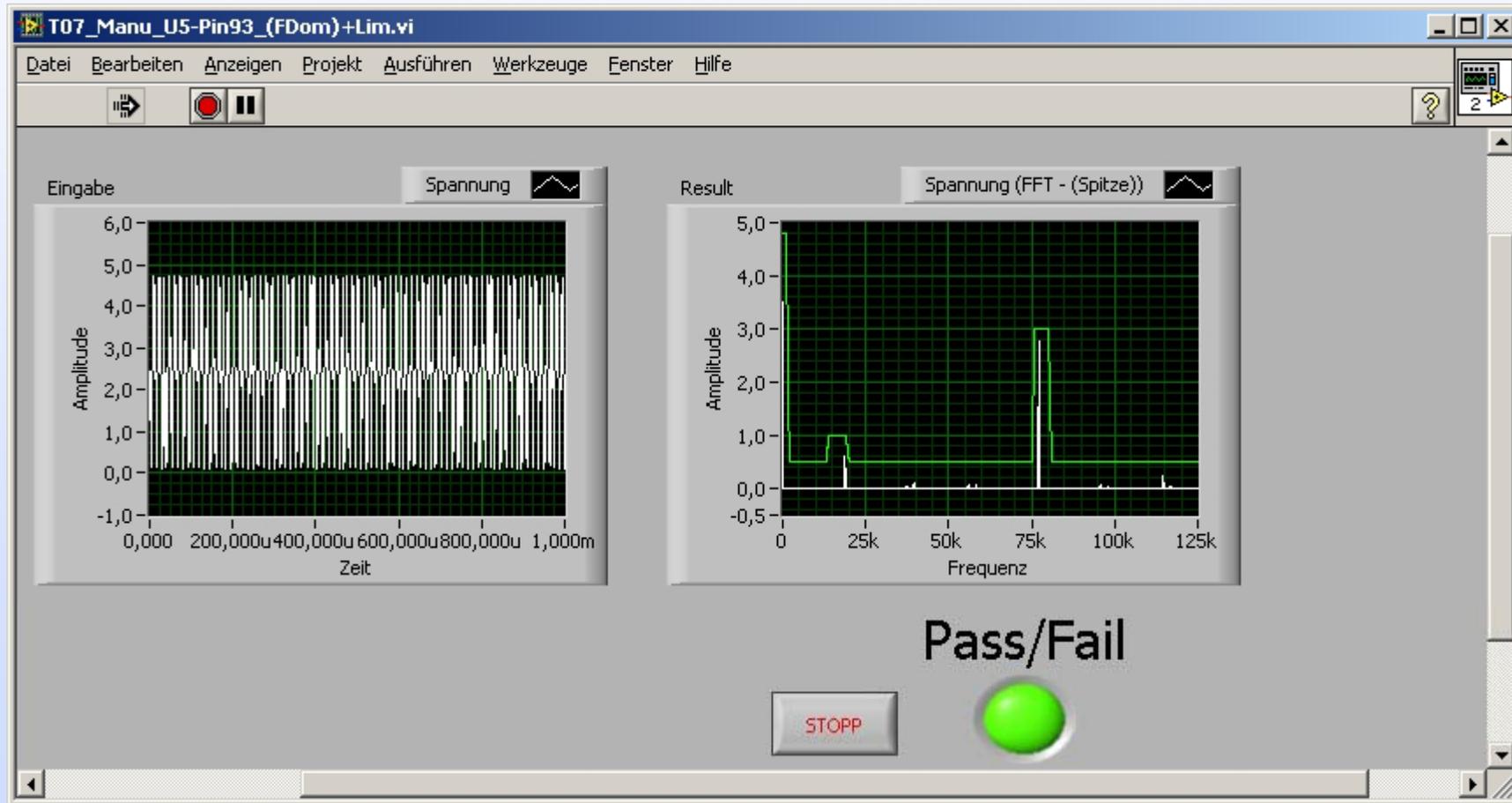
ActiveTest



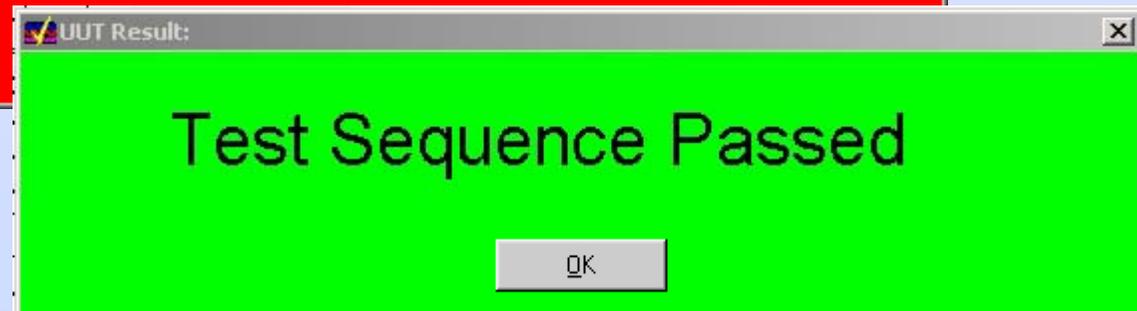
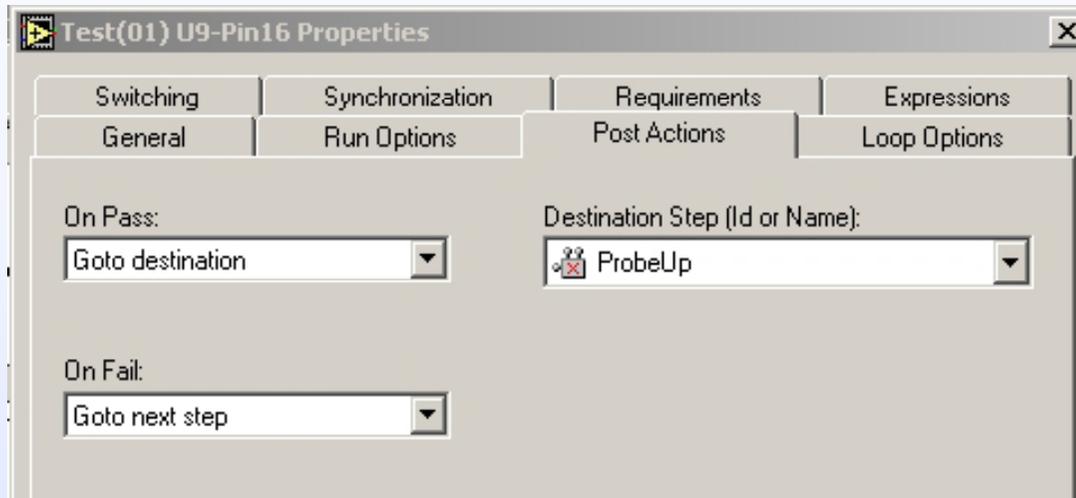
DC Messung



FFT Analyse



Bedingte Sprungbefehle



Gut/Schlecht Vergleich

Dokumentation

UUT Information

Enter UUT Serial Number:

12345

OK Stop

	Time	Operator	Execution Time	Number of Results	UUT Result
ber 2006	13:03:51	administrator	98.1394582 seconds	7	Failed

Failure Chain		
Step	Sequence	Sequence File
Test(06) U5-Pin82	MainSequence	TestBoard_MainSequence.seq

Begin Sequence: MainSequence

(C:\Programme\National Instruments_ELECTRONICA-06\TestStand\TestBoard_MainSequence.seq)

Step	Status	Measurement	Units	Limits		
				Low Limit	High Limit	Comparison Type
Test(01) U9-Pin16	Passed	4.9	V	4.5	5.5	GELE(>= <=)
Test(02) U7-Pin4	Passed	5.0	volt	4.5	5.5	GELE(>= <=)
Test(03) U9-Pin2	Passed	9.4	volt	9.0	10.0	GELE(>= <=)
Test(04) U9-Pin6	Passed	-9.2	volt	-10.0	-9.0	GELE(>= <=)
Test(05) U9-Pin3	Passed	3.2	volt rms	2.5	3.5	GELE(>= <=)
Test(06) U5-Pin82	Failed					
Test(07) U5-Pin93	Failed					

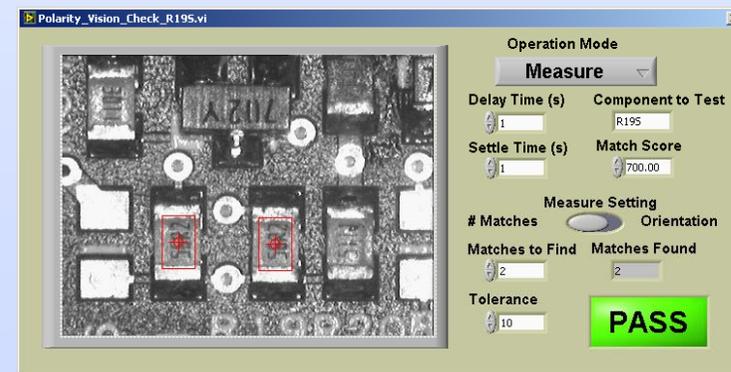
End Sequence: MainSequence

End UUT Report

ActiveVision

Zusatzmodul zu ActiveTest

- Nutzt National Instruments „NI Vision“
Bildverarbeitungspaket
- Integration der Vision-Tests in NI TestStand
- Bauteil-Präsenzerkennung
- Bildmustererkennung
- Verpolungserkennung
- Texterkennung



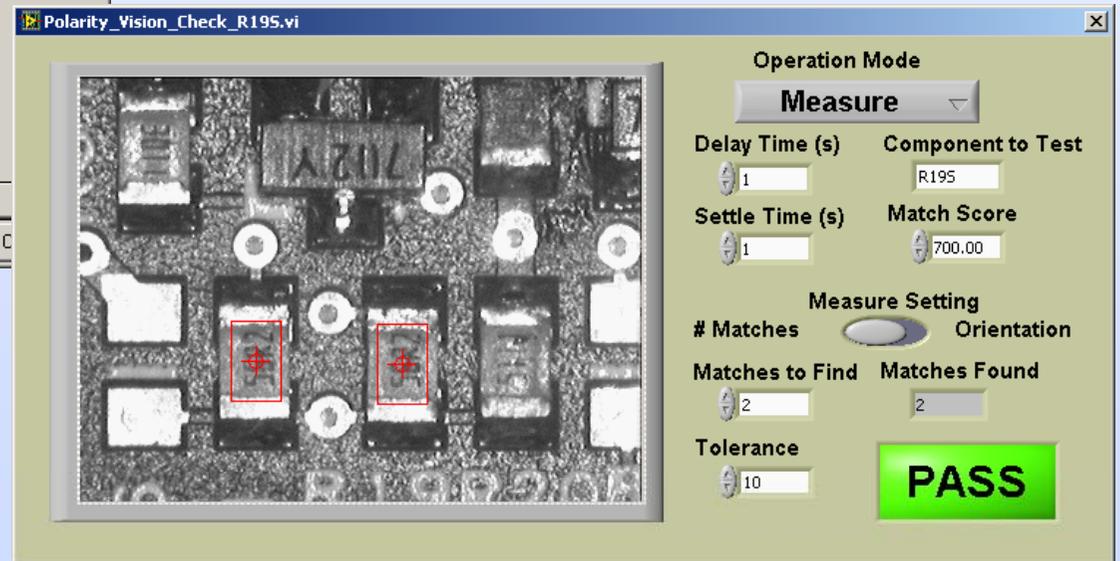
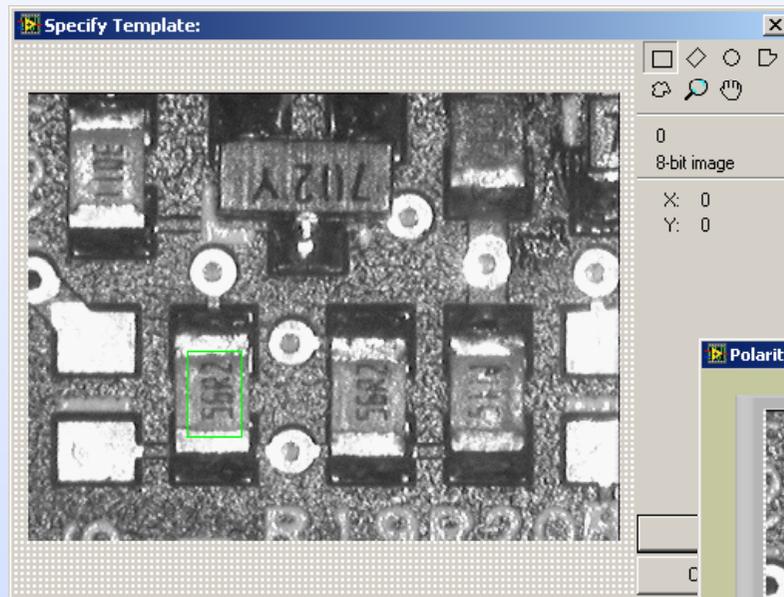
Active Vision Bauteil-Präsenzerkennung

The screenshot shows a software window titled "Presence_Vision_Check_R19.vi". On the left, a grayscale image of a PCB is displayed with a red rectangular box highlighting a component labeled "R19". On the right, a control panel is visible with the following settings:

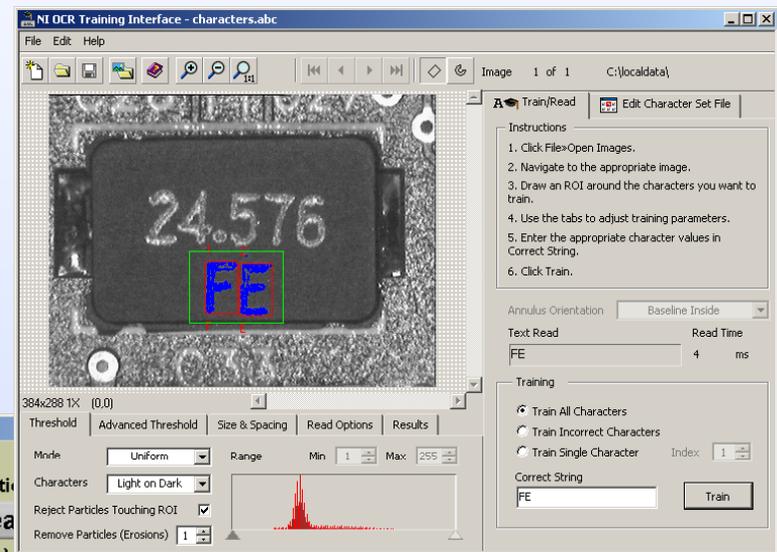
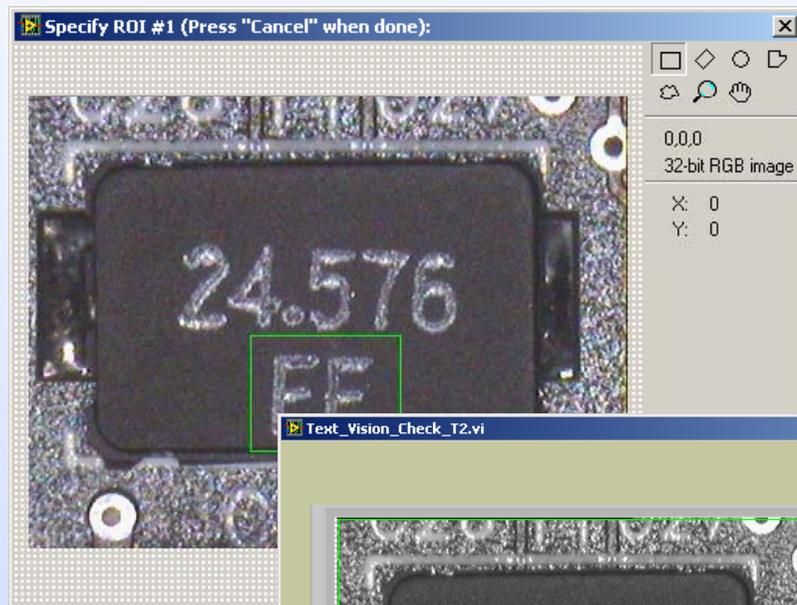
Operation Mode	
Measure	
Delay Time (s)	Component to Test
1	R19
Standard Variation 1	Difference
34.8314	4.8823
Standard Variation 2	Pass/Fail Level
39.7137	10
Settle Time (s)	Toleranz (%)
1	40

A large red button at the bottom of the control panel displays the word "FAIL".

Active Vision Mustererkennung



Active Vision Texterkennung



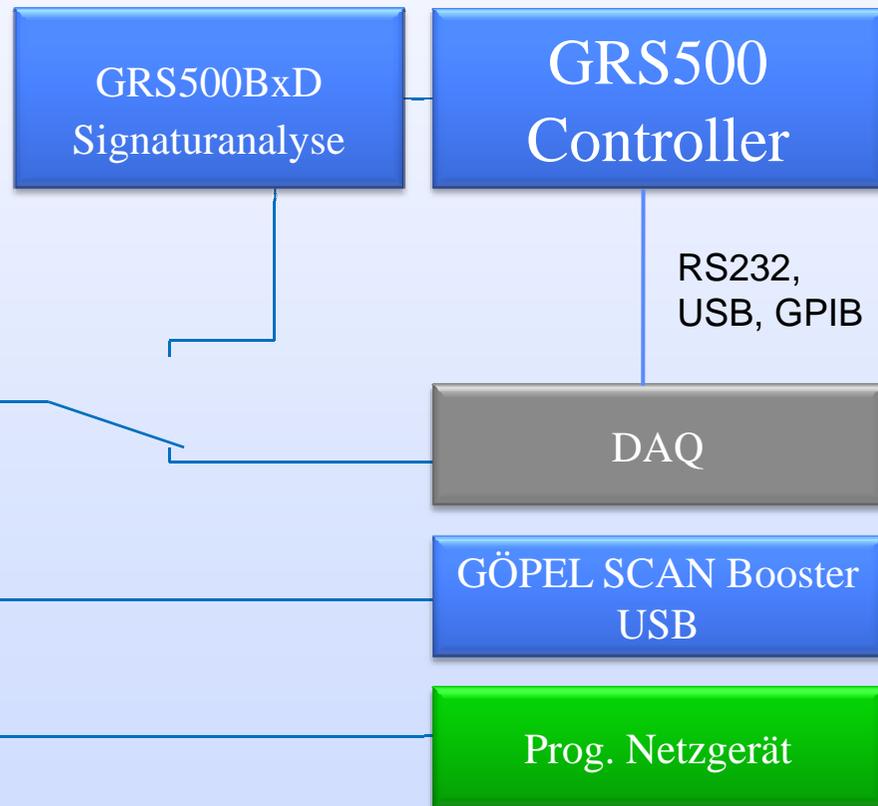
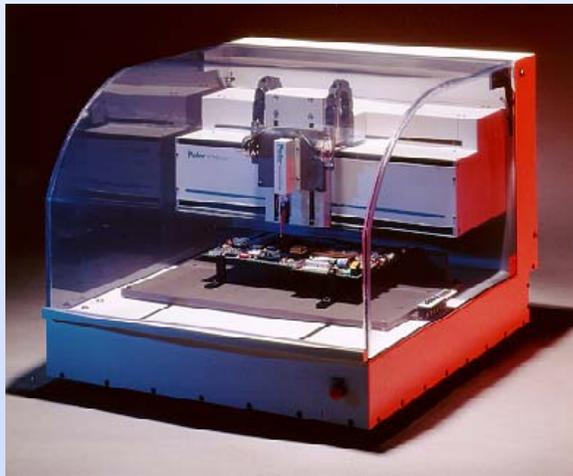
Boundary Scan

Zusatzmodul zu Active Test

- Einbindung von GÖPEL Boundary Scan Hard- und Software
- Integration der Boundary Scan Tests in NI TestStand
- Überprüfung von Logikpegeln über GRS500
- Kombination mit Active Vision



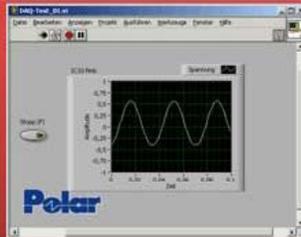
Boundary Scan Test



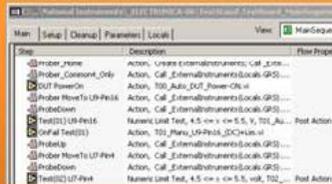
GRS500 Controller



GRS500 Software
incl. CAD-Daten
Visualisierung



National Instruments
LabVIEW



National Instruments
TestStand



GÖPEL CASCON
GALAXY Boundary Scan
Software

Boundary Scan Test

CASCON GALAXY 4.4.2d 1382 - [C:\Programme\CAS4WIN\Uuts\Boundary]

File View Develop SCP Run Options Help

UUT: Boundary Scan Coach - EZScan_SV3
 Test: Drive_D0_High_U1_23
 Batch: ALL_ST_Flash

Serial Number: 594

02.07.2009 18:23:48 UUT: Boundary Scan Coach - EZScan
 =====
 18:23:49 P A S S Elapsed Time 00:00:00.020
 =====

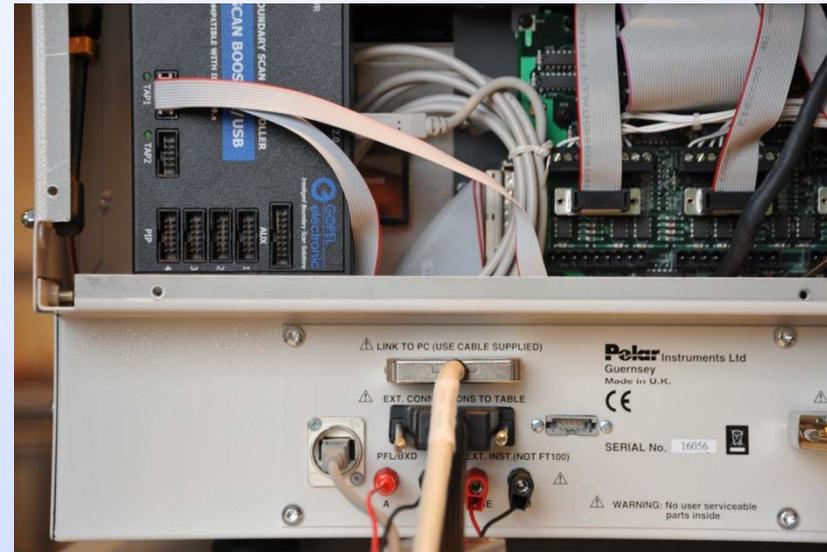
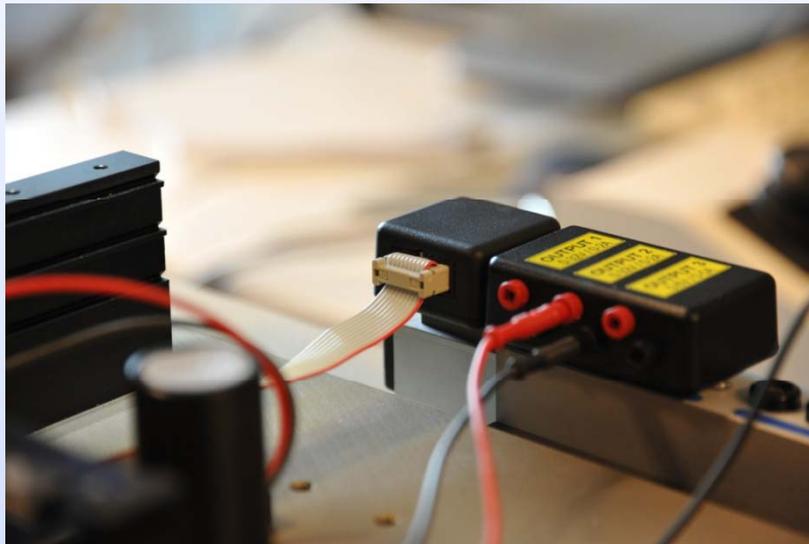
Name	Type	Build	State	Comment
Cluster_U11_DECP1	Cluster	Auto	pass	Cluster test for U11 / output is DECP1
Cluster_U11_DECP2	Cluster	Auto	pass	Cluster test for U11 / output is DECP2
Cluster_U4_A_B	Cluster	Auto	pass	Cluster test for U4A and U4B
Cluster_U4_C	Cluster	Auto	pass	Cluster test for U4C
Drive_D0_High_U1_23	Manually	Auto	pass	Controls LEDs D0 up to D7 with user interaction
Drive_D0_Low_U1_23	Manually	Auto	pass	Controls LEDs D0 up to D7 with user interaction
Drive_D1_High_U1_25	Manually	Auto	pass	Controls LEDs D0 up to D7 with user interaction
Drive_D1_Low_U1_25	Manually	Auto	pass	Controls LEDs D0 up to D7 with user interaction
Drive_D2_High_U1_27	Manually	Auto	pass	Controls LEDs D0 up to D7 with user interaction
Drive_D2_Low_U1_27	Manually	Auto	pass	Controls LEDs D0 up to D7 with user interaction
Drive_D3_High_U1_28	Manually	Auto	pass	Controls LEDs D0 up to D7 with user interaction
Drive_D3_Low_U1_28	Manually	Auto	pass	Controls LEDs D0 up to D7 with user interaction
Drive_D4_High_U1_29	Manually	Auto	pass	Controls LEDs D0 up to D7 with user interaction
Drive_D4_Low_U1_29	Manually	Auto	pass	Controls LEDs D0 up to D7 with user interaction
Drive_D5_High_U1_30	Manually	Auto	pass	Controls LEDs D0 up to D7 with user interaction
Drive_D5_Low_U1_30	Manually	Auto	pass	Controls LEDs D0 up to D7 with user interaction
Drive_D6_High_U1_32	Manually	Auto	pass	Controls LEDs D0 up to D7 with user interaction
Drive_D6_Low_U1_32	Manually	Auto	pass	Controls LEDs D0 up to D7 with user interaction
Drive_D7_High_U1_33	Manually	Auto	pass	Controls LEDs D0 up to D7 with user interaction
Drive_D7_Low_U1_33	Manually	Auto	pass	Controls LEDs D0 up to D7 with user interaction
Execute_Exec	Manually	Auto	pass	Starts an exe-file from CASLAN.
FLASH U10 (AMD)	FLASH	Auto	pass	Flash programming of U10 including Action Flow (Flash is from AMD)
FLASH U10 (ST)	FLASH	Auto	pass	Flash programming of U10 including Action Flow (Flash is from ST Micro)
Infrastructure	Infra structure	Auto	pass	Controls the function of the Testbus.
INTERCONNECTION	Interconnection	Auto	pass	Test of the Boundary scan connections
INTERCONNECTION_NO_U3	Interconnection	Auto	pass	Test of the Boundary scan connections (U3 is disabled)
LED Check Interaction	Manually	Auto	pass	Controls LEDs D0 up to D7 with user interaction
LED Check	Manually	Auto	pass	Controls LEDs D0 up to D7
RAM U9	RAM	Auto	pass	RAM test for U9 including Go / NoGo test
SVF U1_Clear	SVF (FPGA/PLD)	Auto	pass	SVF Programming of U1 (erases U1).
SVF U1_Program	SVF (FPGA/PLD)	Auto	pass	SVF Programming of U1 (programs U1).
SVF U2_Clear	SVF (FPGA/PLD)	Auto	pass	SVF Programming of U2 (erases U2).
SVF U2_Program	SVF (FPGA/PLD)	Auto	pass	SVF Programming of U2 (programs U2).
TAP_Reset	Manually	Auto	pass	version 1.2
TCK Check Up	Manually	Auto	pass	Verifies the Q1 clock signal for H and L at U1 and U2. No frequency measurement.
Test_Clock	Manually	Auto	pass	

Number of DRShifts: 2

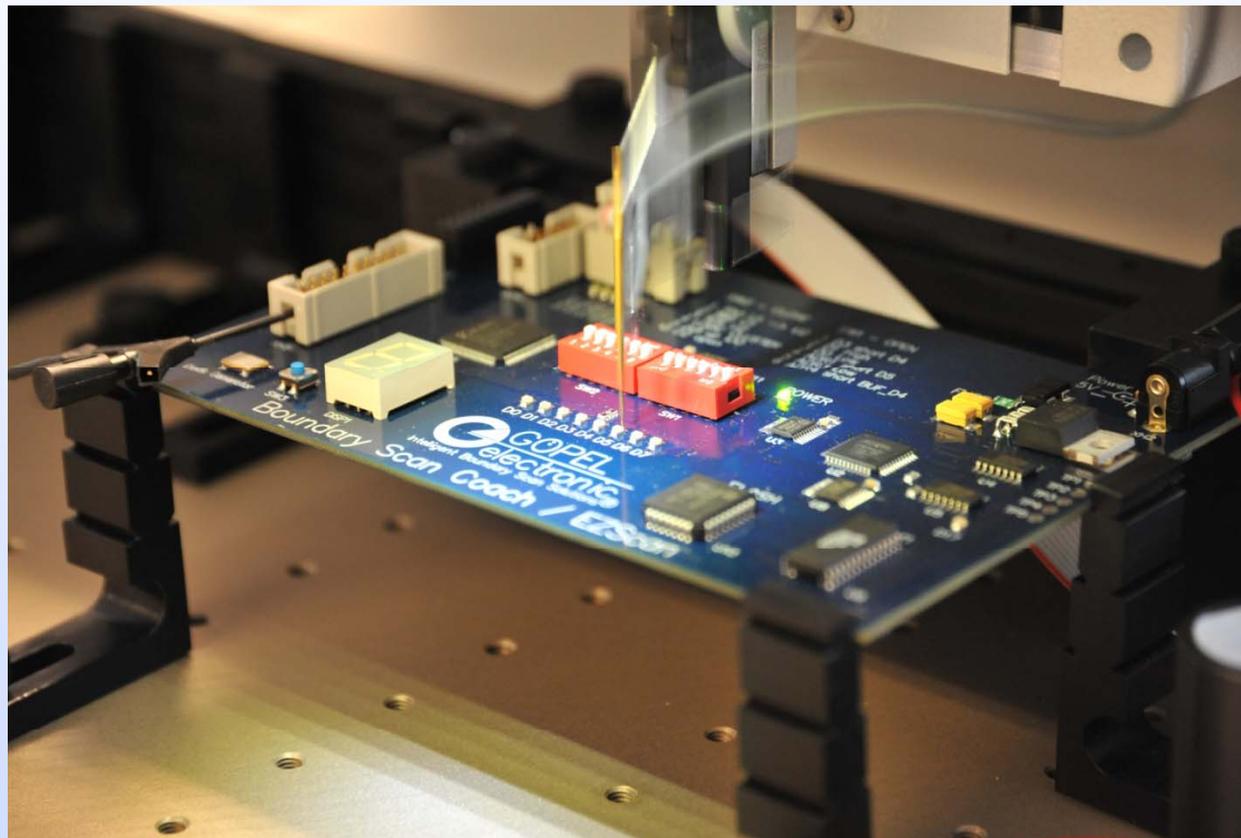
Board UUT: cmd> EXECUTE ready * TCK 30.00 MHz >> actual 16.13 MHz Testbyte ON 52H

Die Erstellung von Boundary Scan Tests erfolgt in gewohnter Weise über GÖPEL CASCON GALAXY

Boundary Scan Test Integration in GRS500



Boundary Scan Test



Boundary Scan Test in Kombination mit Logikpegelmessungen über den GRS500

